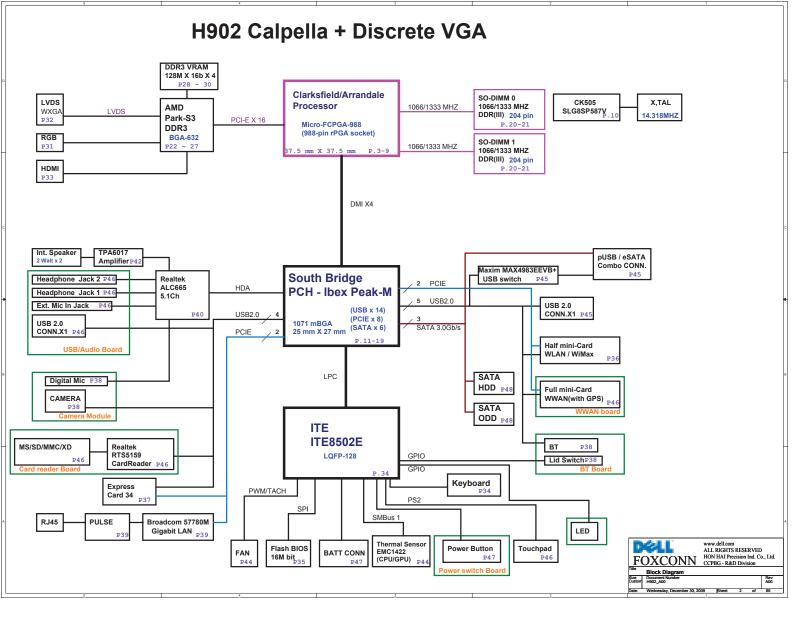
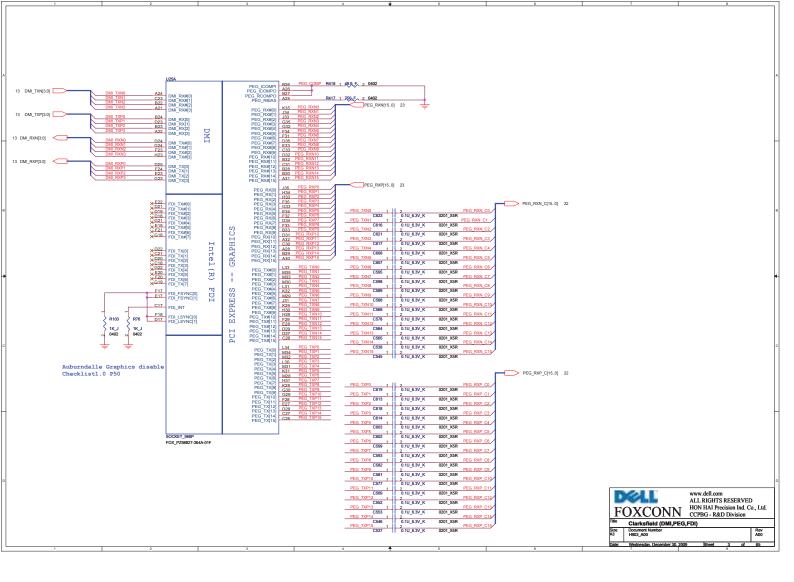
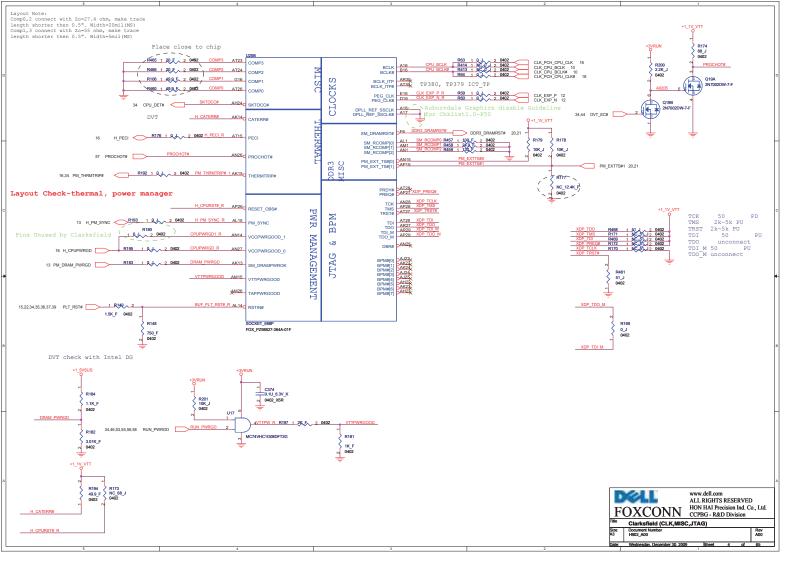
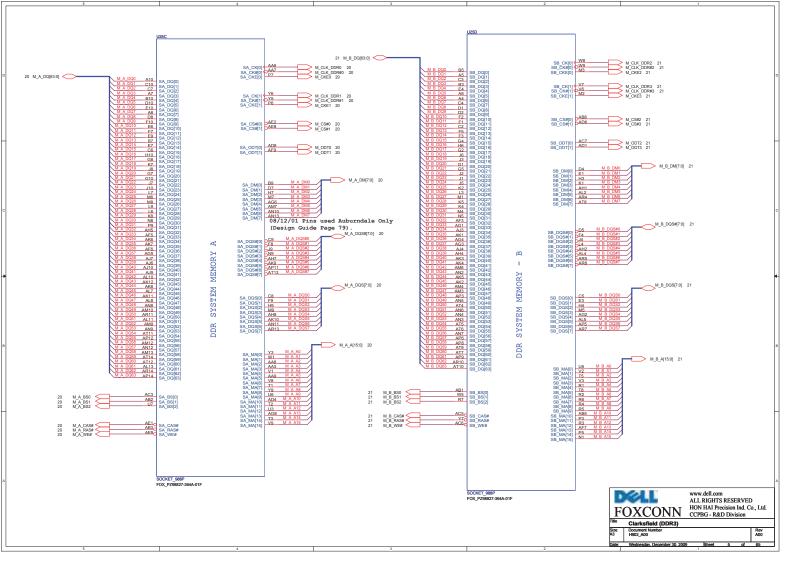
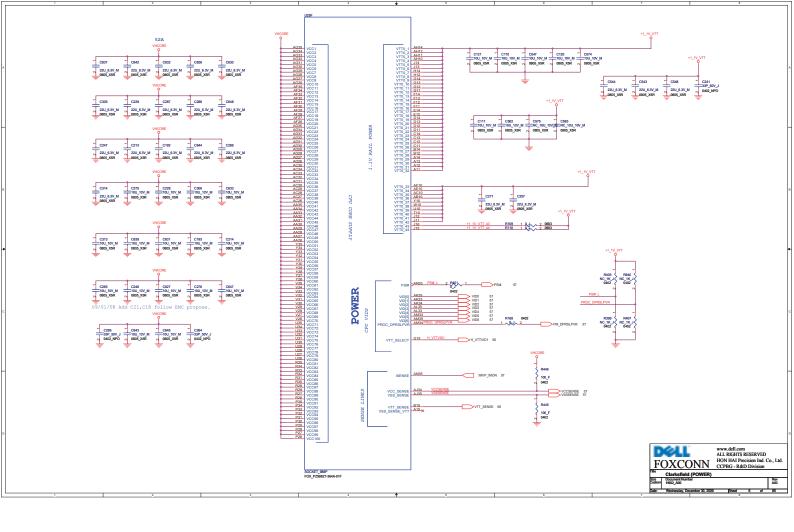
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	Schematics Page	Index	(Title /	Revi	ision / Change Date)		
age	Title of Schematics Page	Rev.	Date	Page	Title of Schematics Page	Rev.	Date
ĺ	Schematics Page Index	A00	09'12'25		WLAN/WiMAX Mini-PCIECard	A00	09'12'25
	Block Diagram	A00	09'12'25		EXPRESS CARD	A00	09'12'25
	Clarksfield (DMI, PEG, FDI)	A00	09'12'25	38	BT & CAMERA/Dig MIC CON	A00	09'12'25
	Clarksfield (CLK, MISC, JTAG)	A00	09'12'25	39	Broadcom LAN(BCM57780M)	A00	09'12'25
	Clarksfield (DDR3)	A00	09'12'25	40	Audio (CODEC & POWER)	A00	09'12'25
6	Clarksfield (POWER)	A00	09'12'25	41	Audio (HP,EXT MIC)	A00	09'12'25
7	Clarksfield (GRAPHICS POWER)	A00	09'12'25	42	Audio (SPKR)	A00	09'12'25
8	Clarksfield (GND)	A00	09'12'25		Audio (MUTE)	A00	09'12'25
9	Clarksfield (RESERVED)	A00	09'12'25	44	FAN/Thermal/G Sensor	A00	09'12'25
	CLOCK GEN	A00	09'12'25		USB2.0 & e-SATA	A00	09'12'25
Ĺ	PCH (HDA, JTAG, SAT)	A00	09'12'25		DB board connector (MB)	A00	09'12'25
2	PCH (PCI-E, SMBUS, CLK)	A00	09'12'25		PWR BTN & BT & LED DB	A00	09'12'25
3	PCH (DMI, FDI, GPIO)	A00	09'12'25		SATA HDD/ODD	A00	09'12'25
1	PCH (LVDS, DDI)	A00	09'12'25		Power Design Diagram	A00	09'12'25
5	PCH (PCI, USB, NVRAM)	A00	09'12'25		DCIN & Battery	A00	09'12'25
5	PCH (GPIO, VSS NCTF, RSVD)	A00	09'12'25		MAX8731A Smart Charger	A00	09'12'25
7	PCH (POWER) 1/2	A00	09'12'25		MAX17020 (+3 3V/+5V)	A00	09'12'25
		A00	09'12'25			A00	09'12'25
9	PCH (POWER) 2/2	A00			SYS Power+1 1VVTT/+1 05V	A00	
	PCH (VSS)	A00	09'12'25		DDR3 Power (+1 5V/+0 75V)	A00	09'12'25
0	DDR3(SO-DIMM 0) 1/2		09'12'25		CPU Power VHCORE		09'12'25
	DDR3 (SO-DIMM 1) 2/2	A00	09'12'25		CPU Power DRV-PHASE3	A00	09'12'25
	VGA (PCI-E) 1/6	A00	09'12'25		VGA Power(ATI VDD)	A00	09'12'25
	VGA (STRAP) 2/6	A00	09'12'25		SYS Power +1 8V	A00	09'12'25
	VGA (IO) 3/6	A00	09'12'25		Others power plane	A00	09'12'25
	VGA (DDR3) 4/6	A00	09'12'25		HOLE	A00	09'12'25
	VGA (DP) 5/6	A00	09'12'25		History (1)	A00	09'12'25
	VGA (POWER) 6/6	A00	09'12'25		History (2)	A00	09'12'25
3	VRAM (DDR3) 1/3	A00	09'12'25		History (3)	A00	09'12'25
)	VRAM (DDR3) 2/3	A00	09'12'25		Power History (1)	A00	09'12'25
1	VRAM (BYPASS) 3/3	A00	09'12'25		Power History (2)	A00	09'12'25
.	CRT	A00	09'12'25				
2	LVDS	A00	09'12'25				
3	HDMI	A00	09'12'25	68			
	EC+KBC(IT8502E)	A00	09'12'25	69			
, \neg	Flash ROM/SPI	A00	09'12'25	70			
roj	ect Code & Schematics Subject: H902 Ma			 			
				PCB	1P-009C500-8000 (HANNSTAR)		
				i	B P/N: 1P-1098J01-8000 (IRIS) 1P-1098501-8000 (HANNSTAR) 1P-1098201-8000 (NANYA) DB P/N: 1P-1098J00-8000 (IRIS) 1P-1098500-8000 (HANNSTAR)	P. Leader	Check by
				P/B 1	1P-1098200-8000 (NANYA) 1P-1098J02-8000 (IRIS) 1P-1098502-8000 (HANNSTAR) 1P-1098202-8000 (NANYA)		ONN CCPB
						Size Document Num	nber

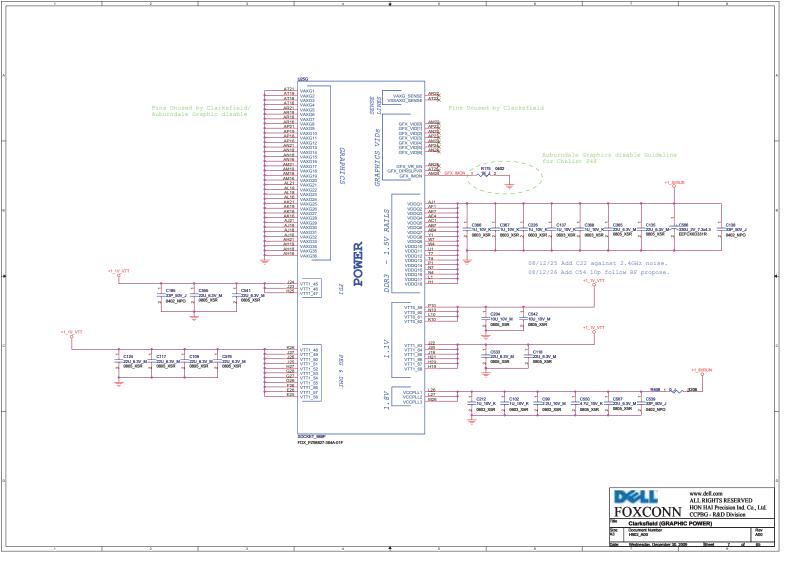


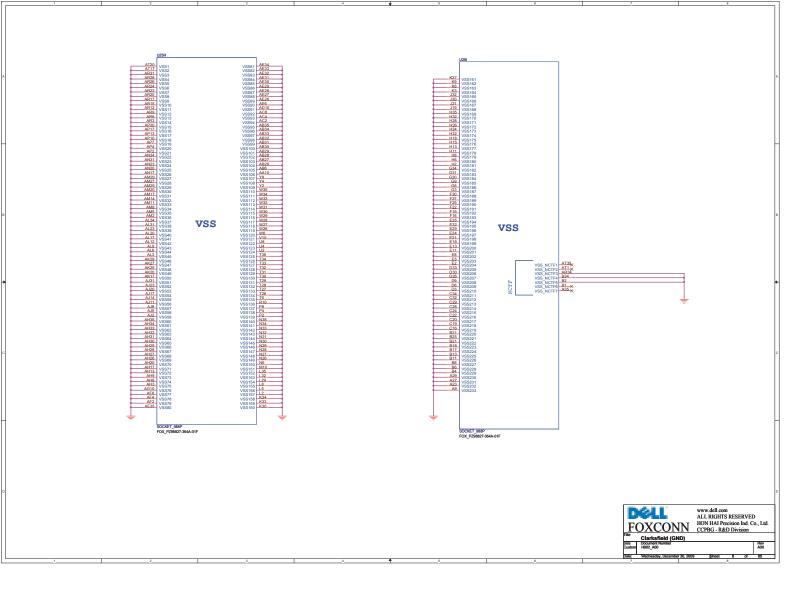


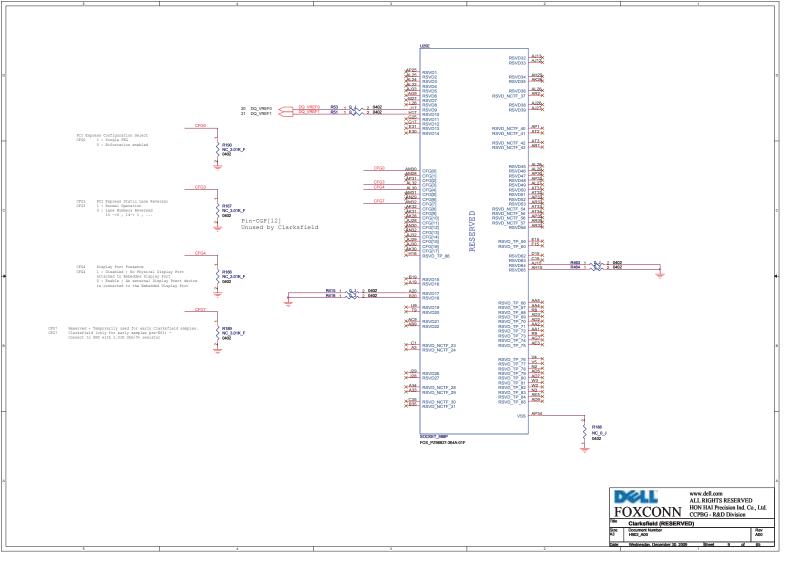


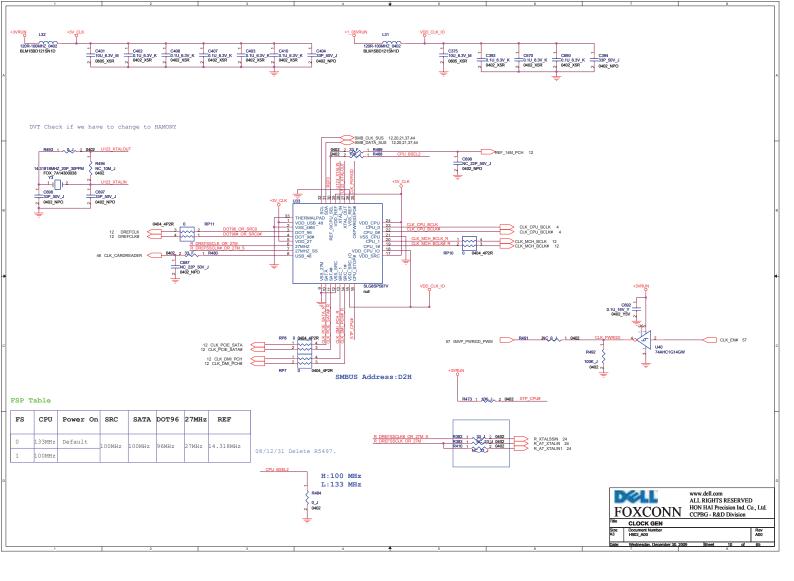


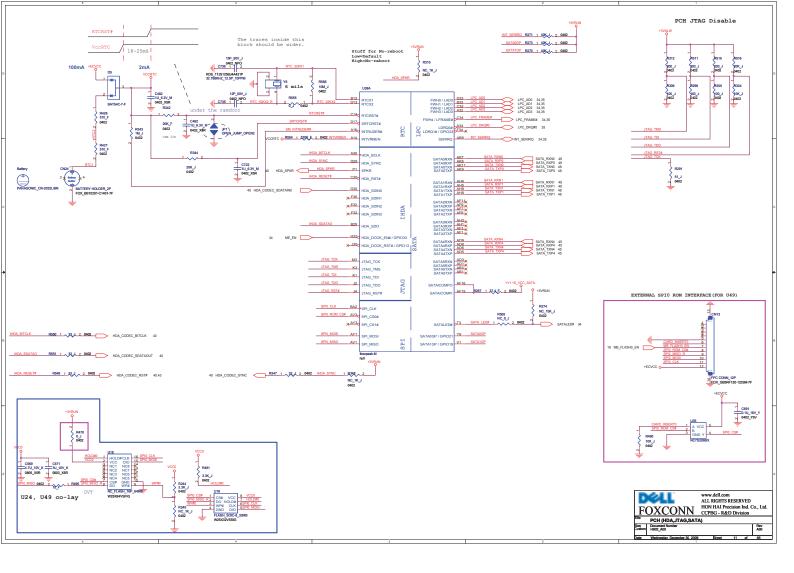


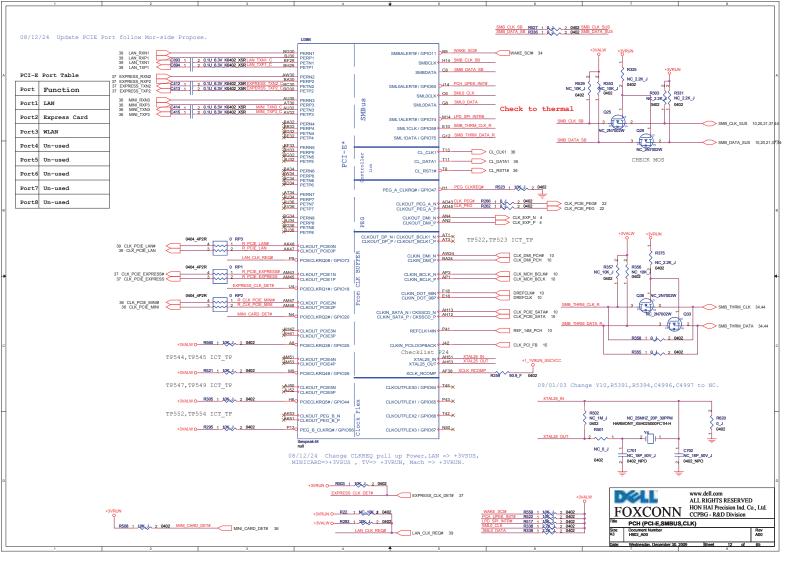


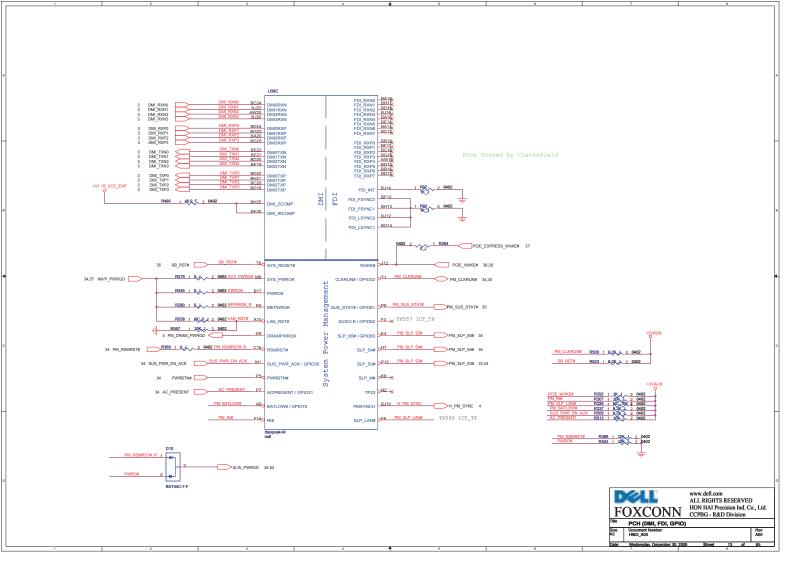


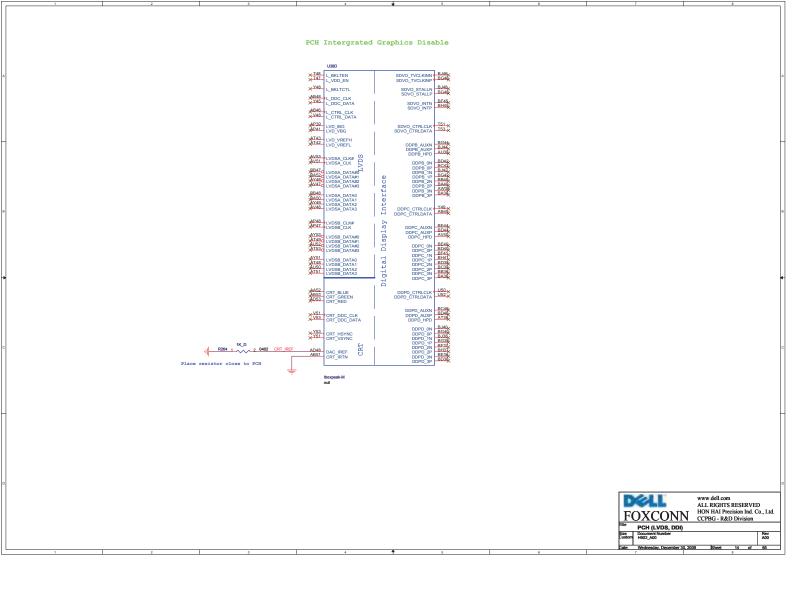


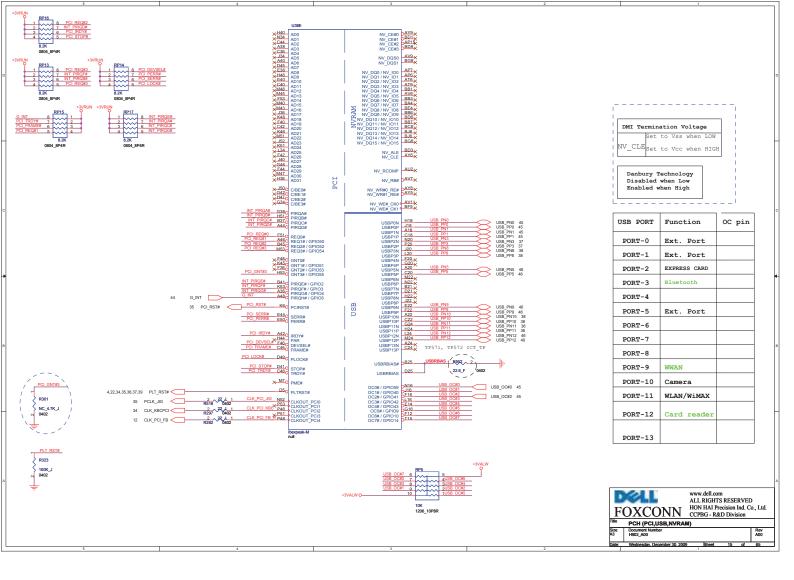


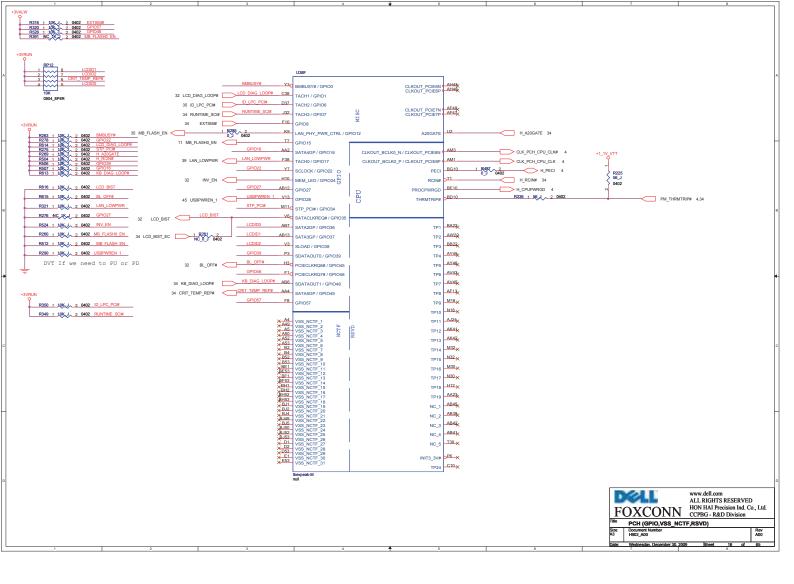


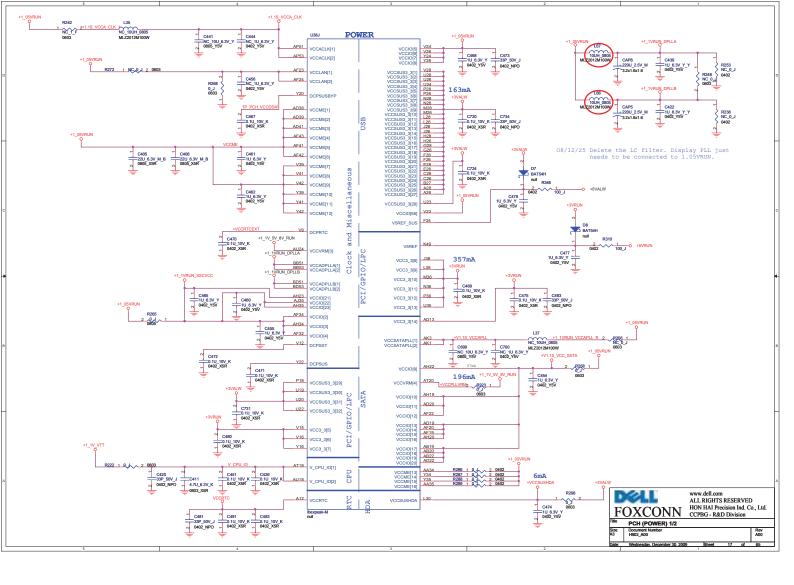


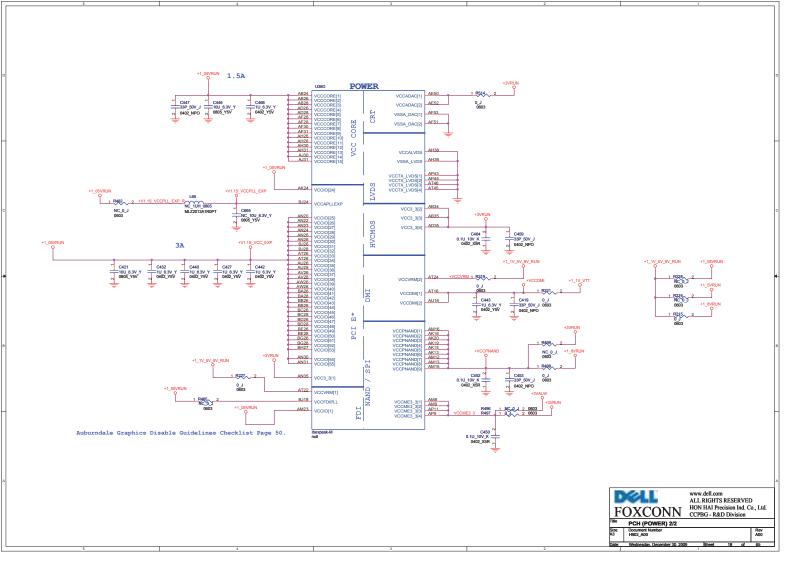


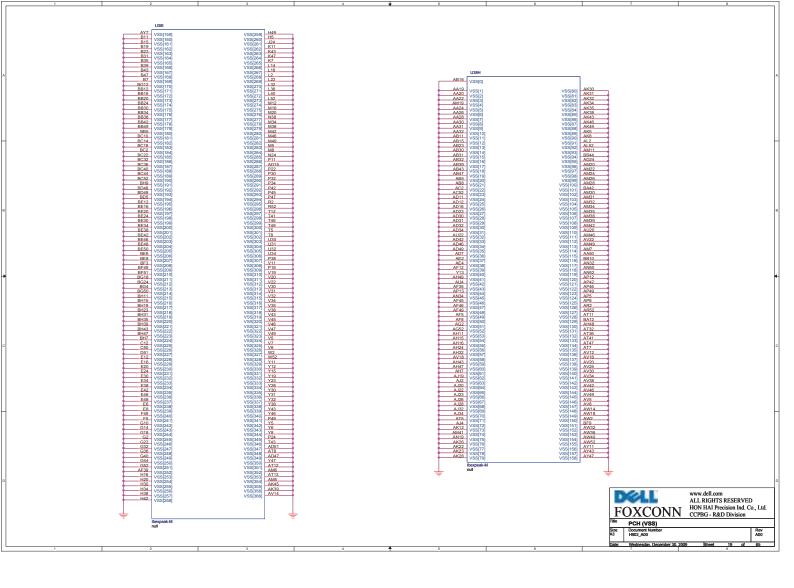


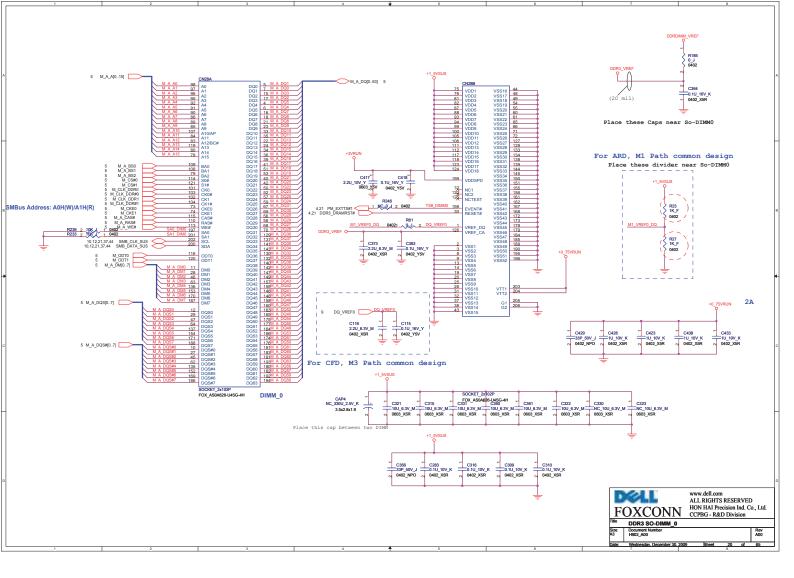


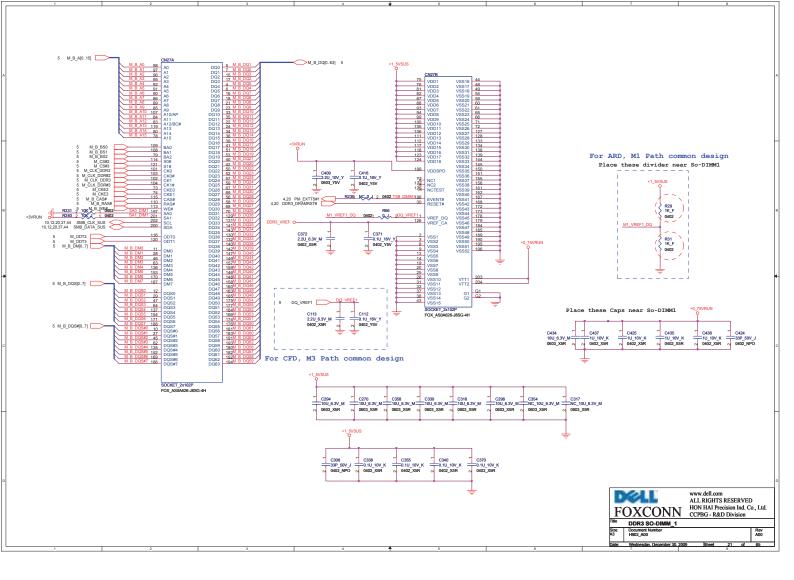


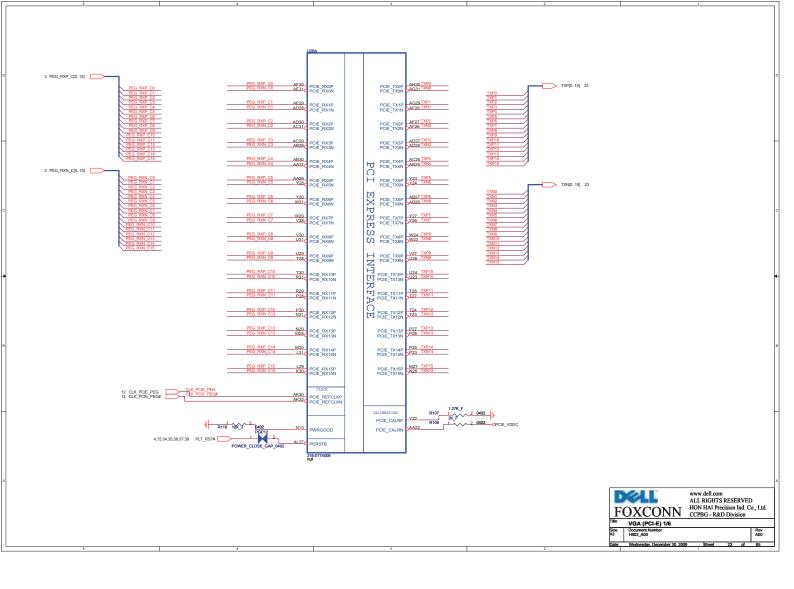


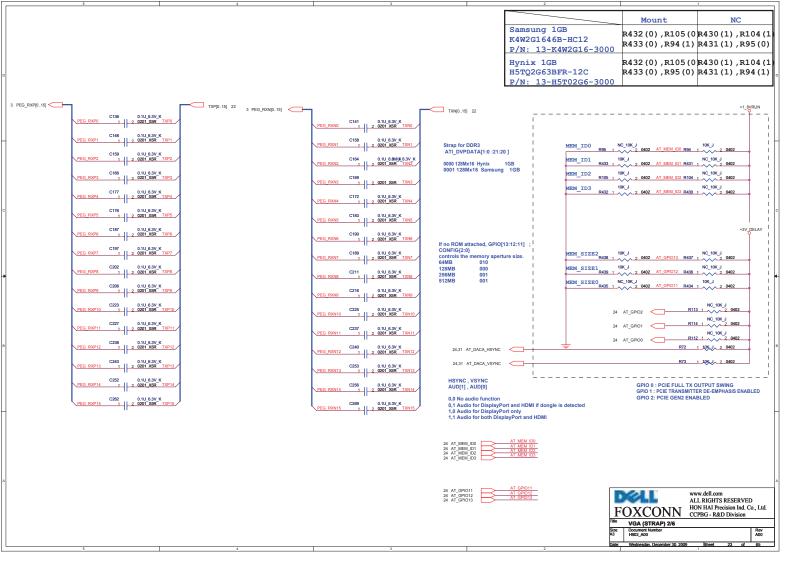


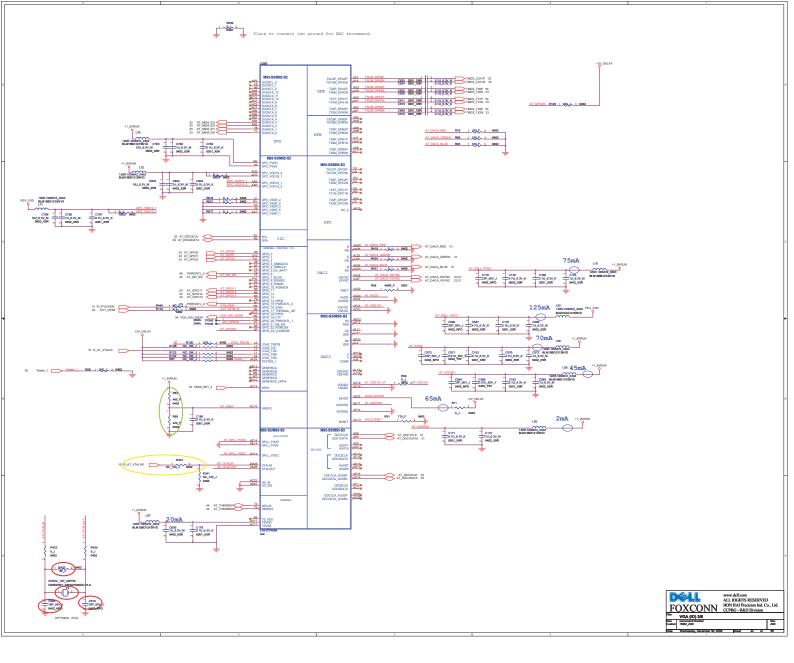


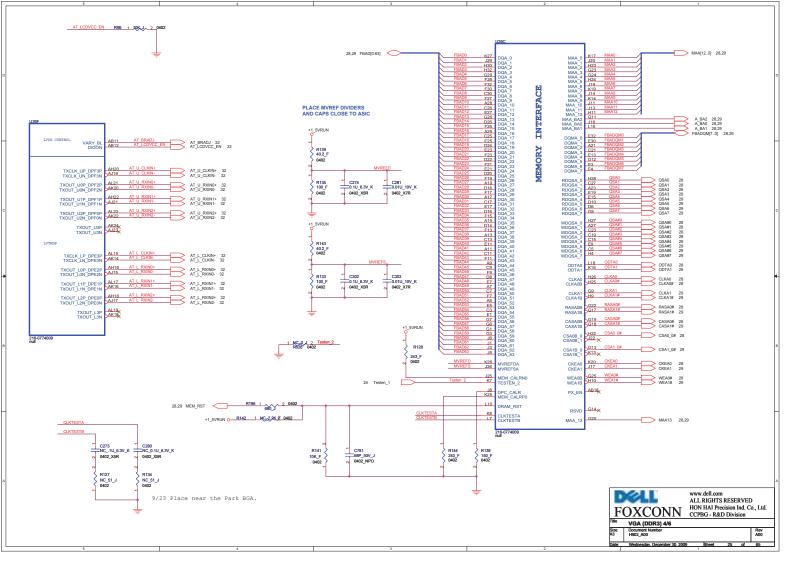


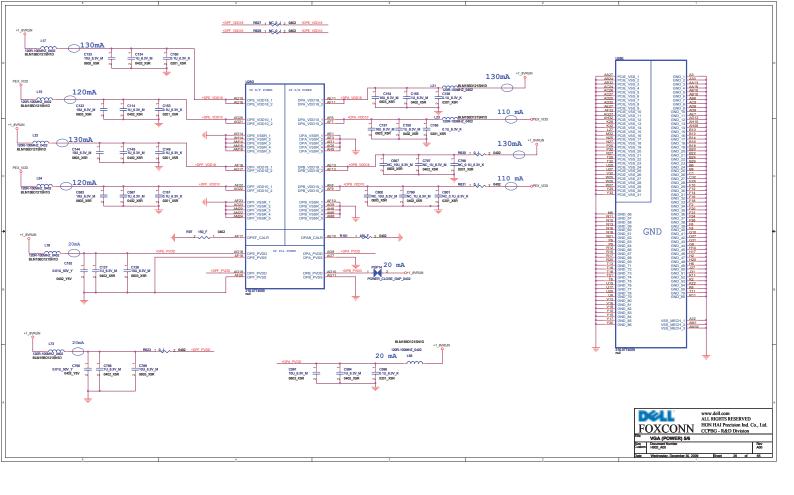


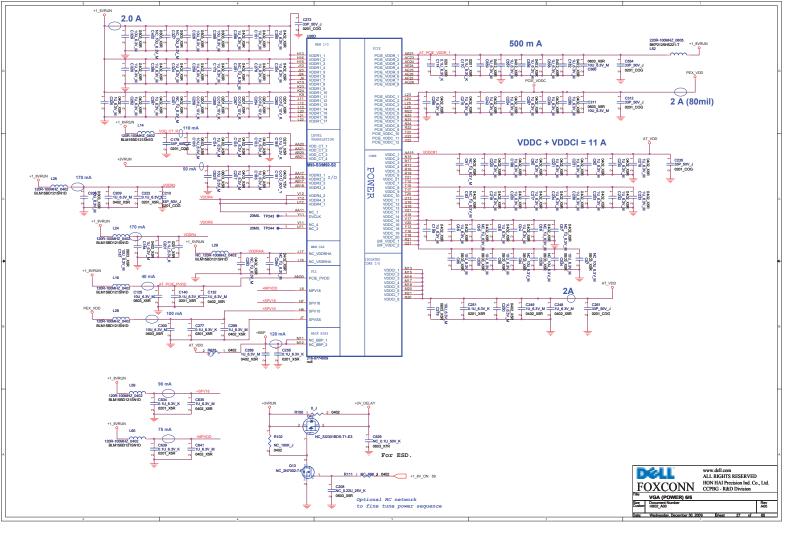


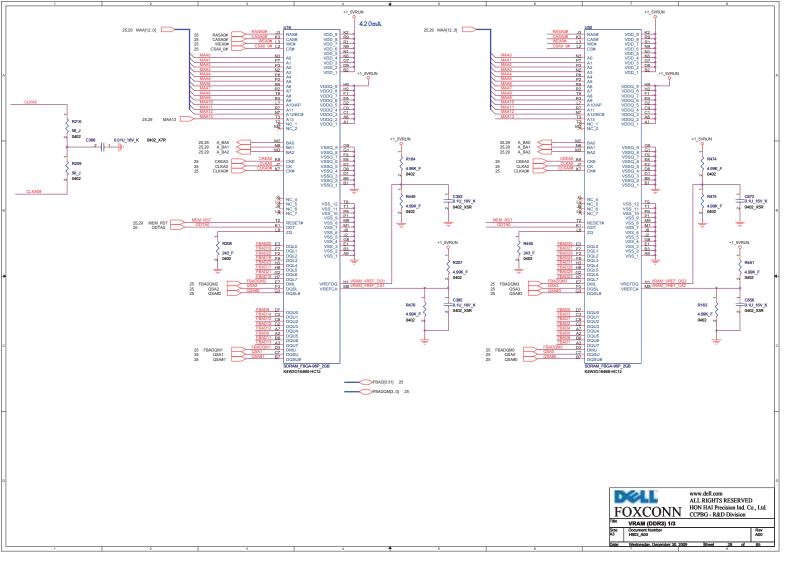


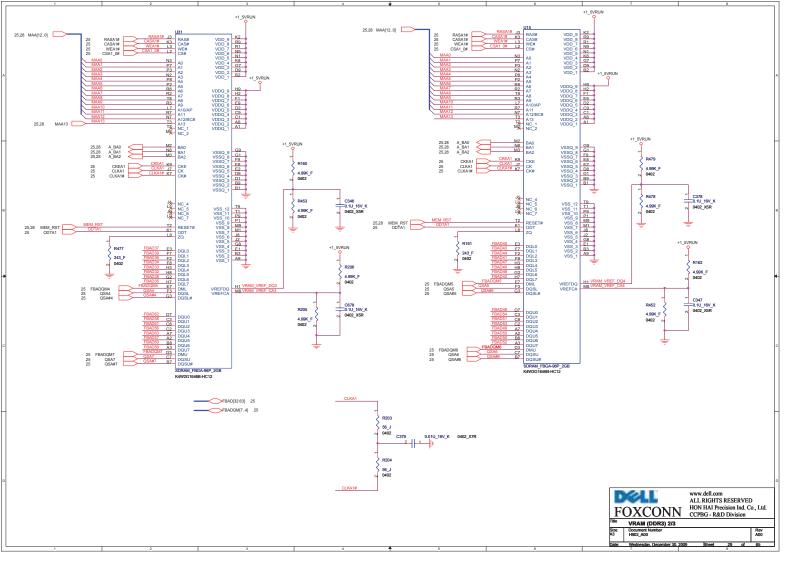


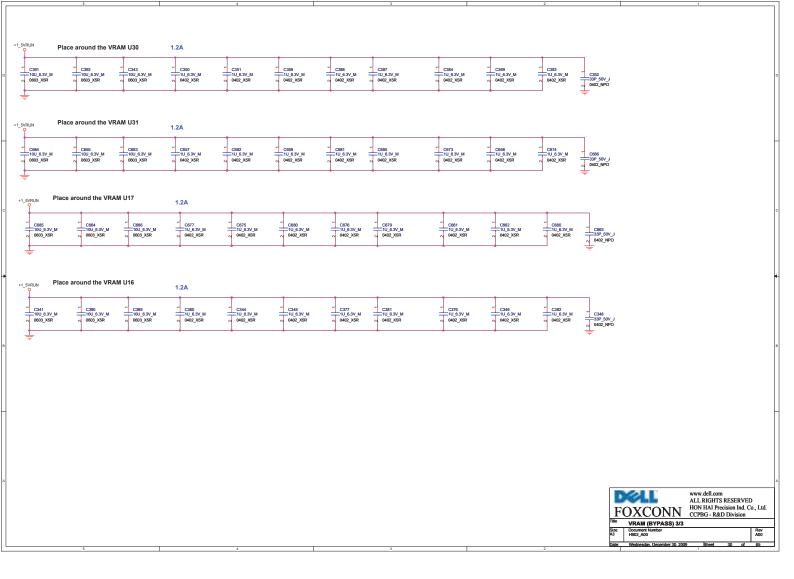


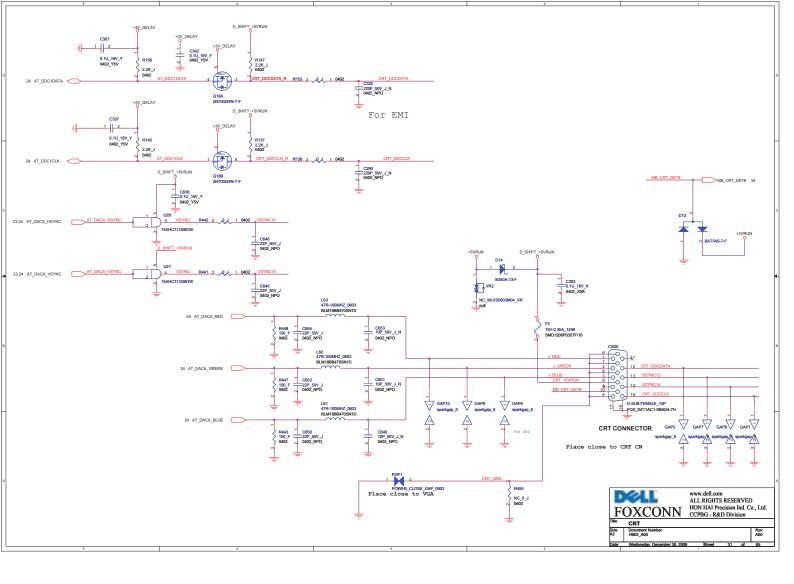


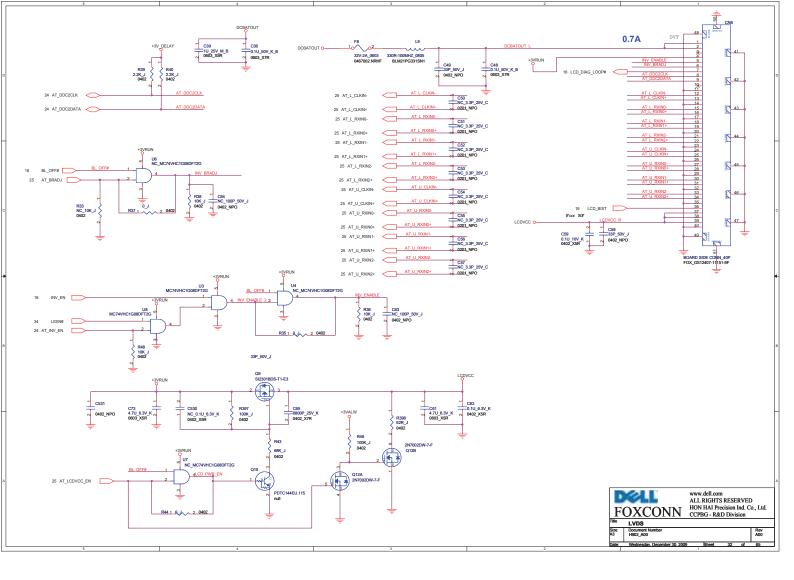


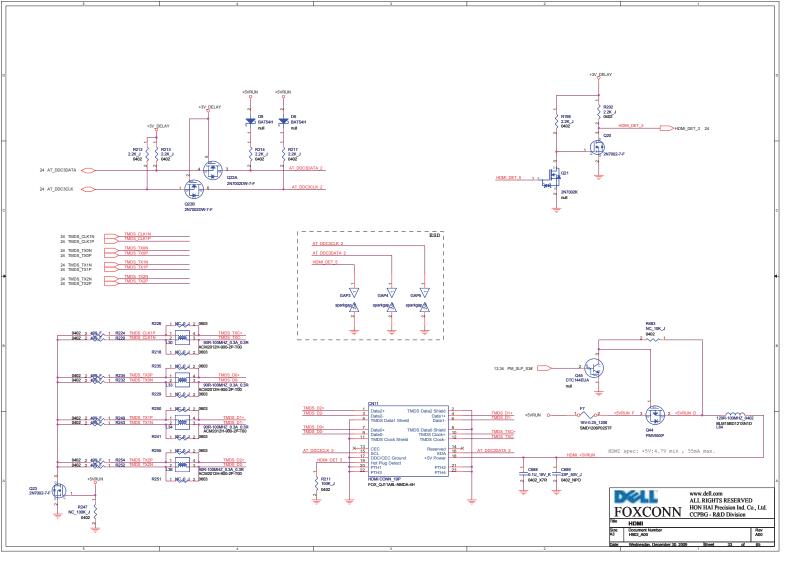


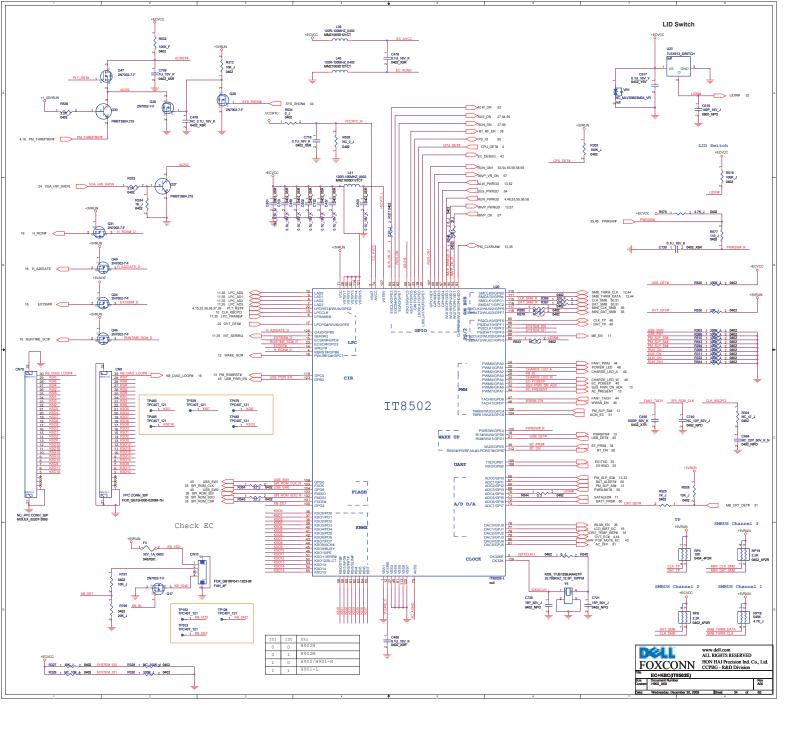


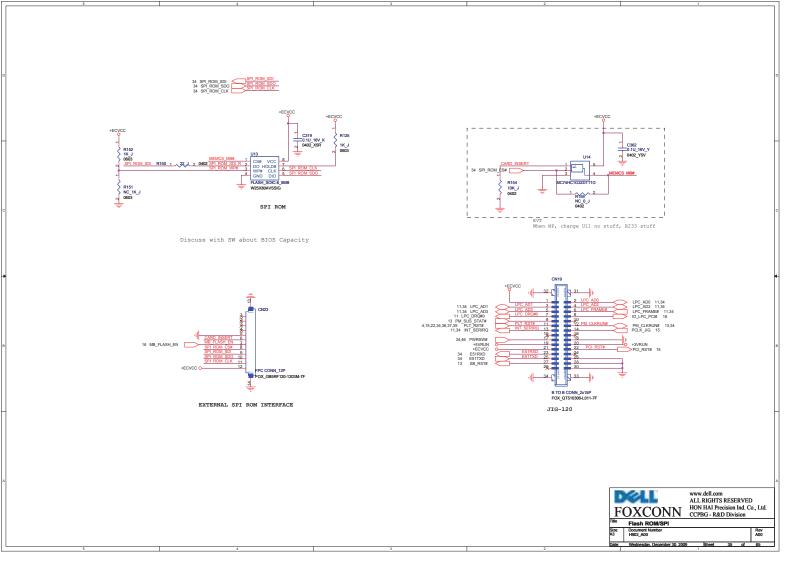


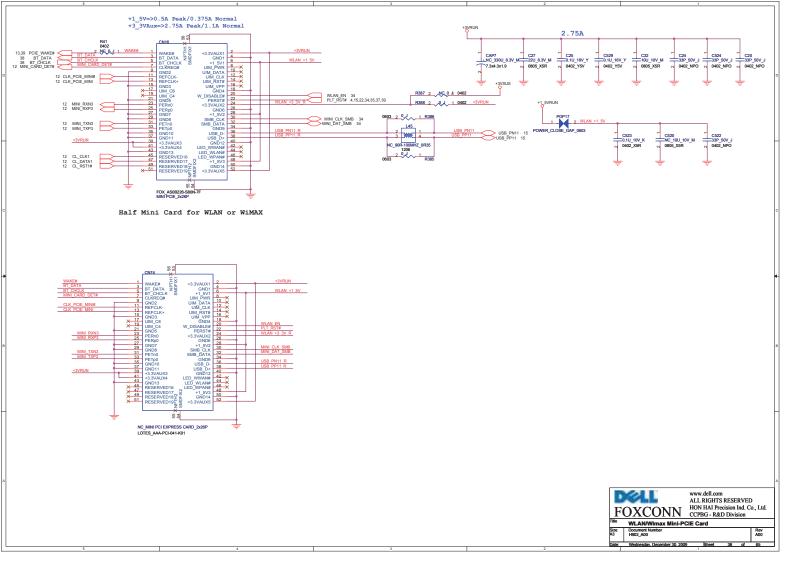


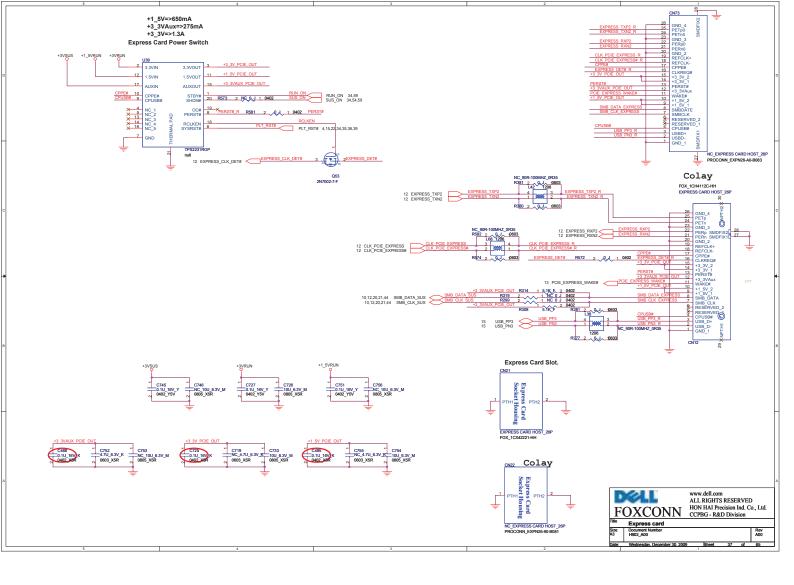


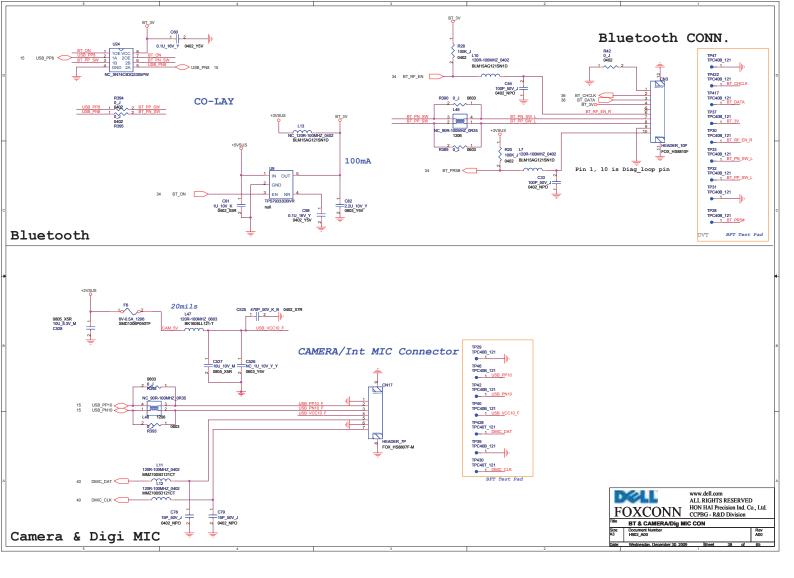


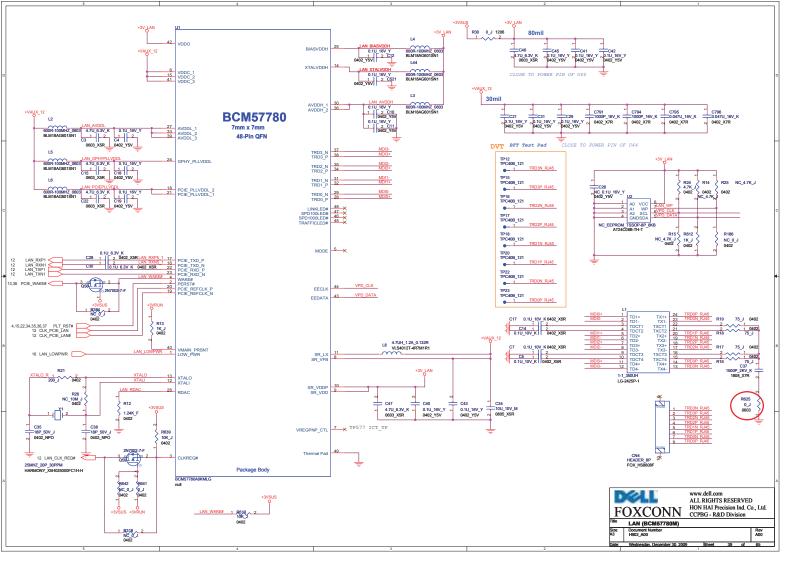


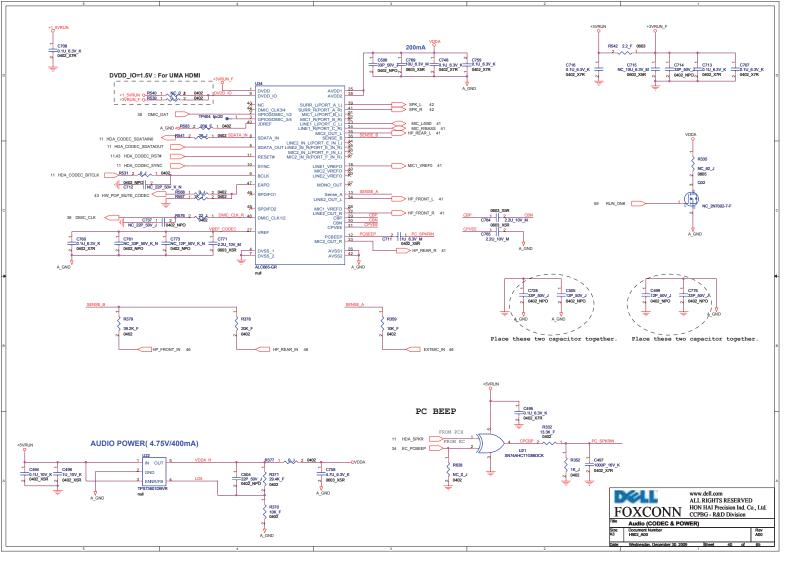


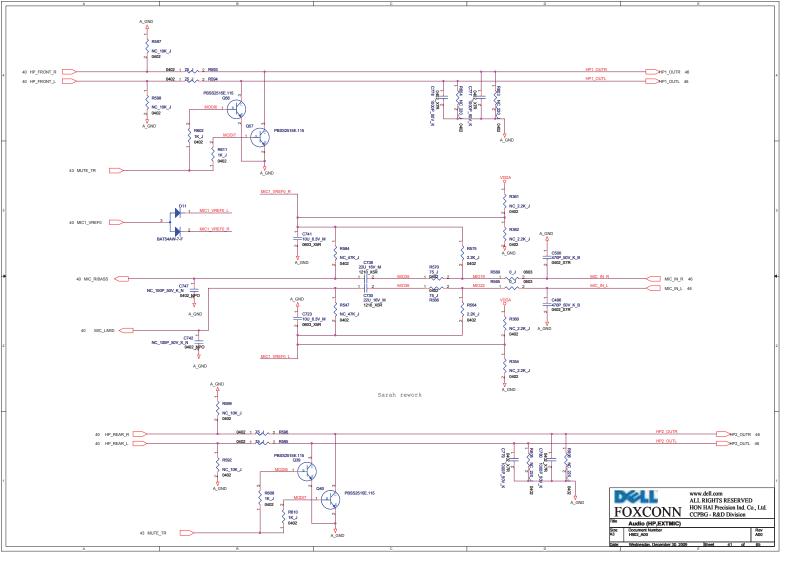


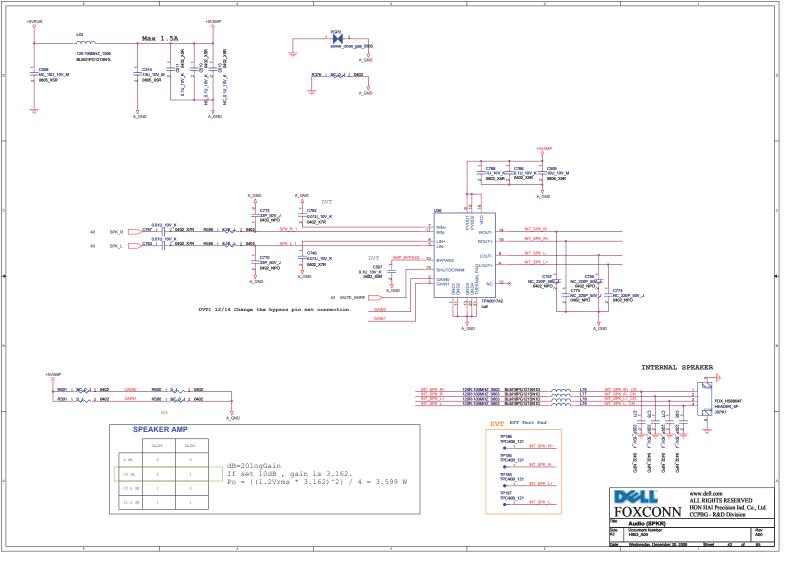


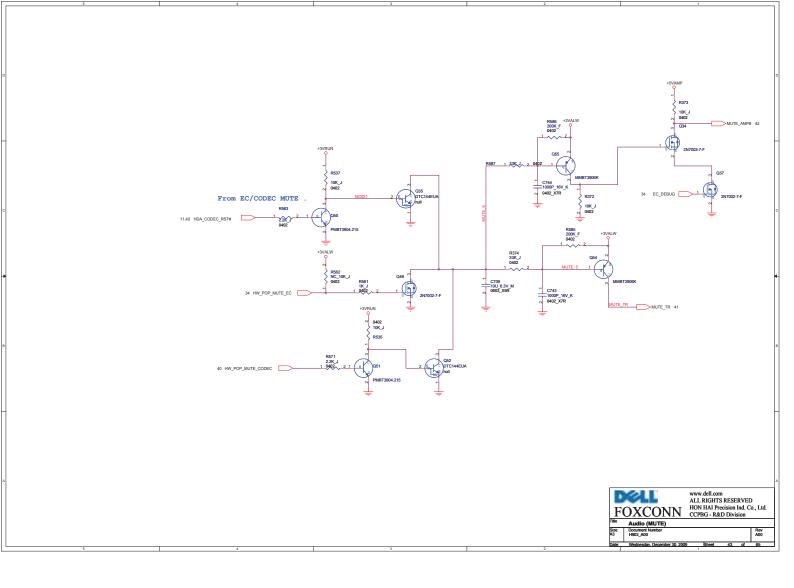


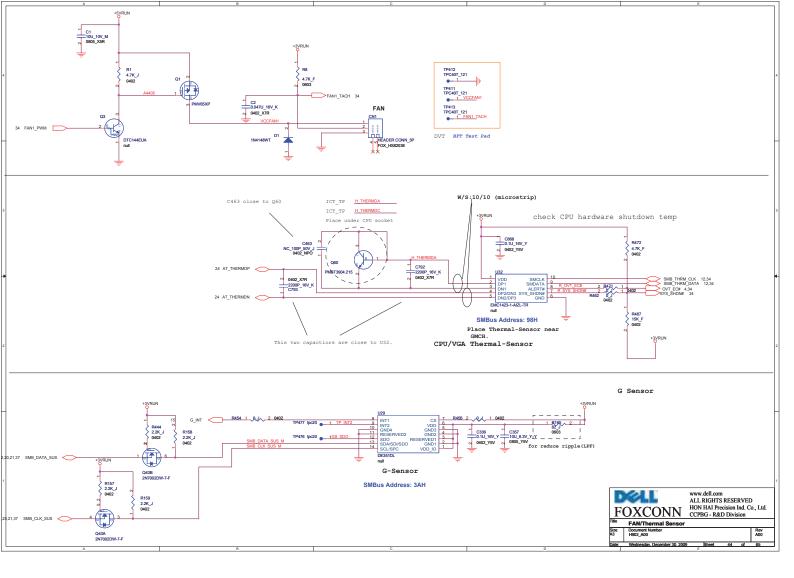


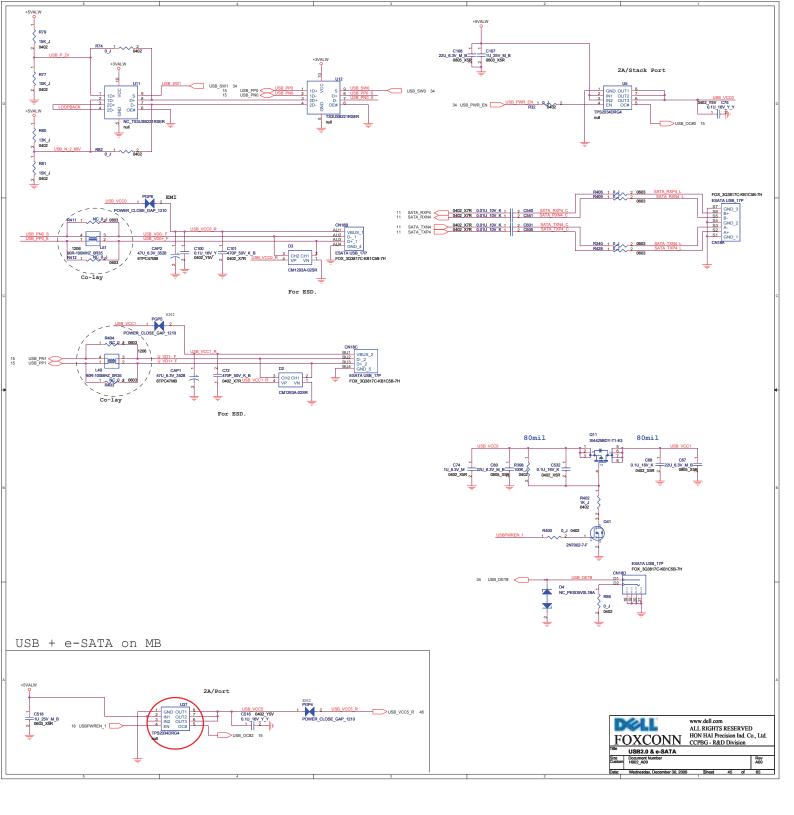


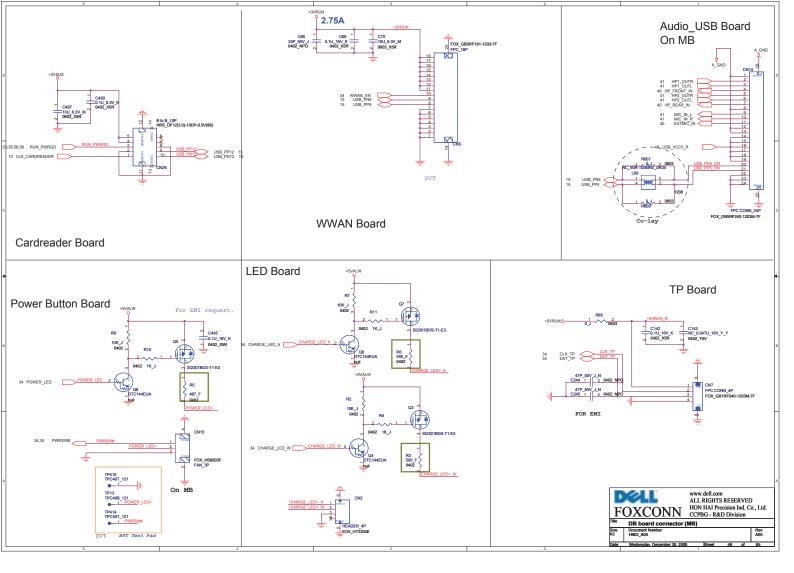


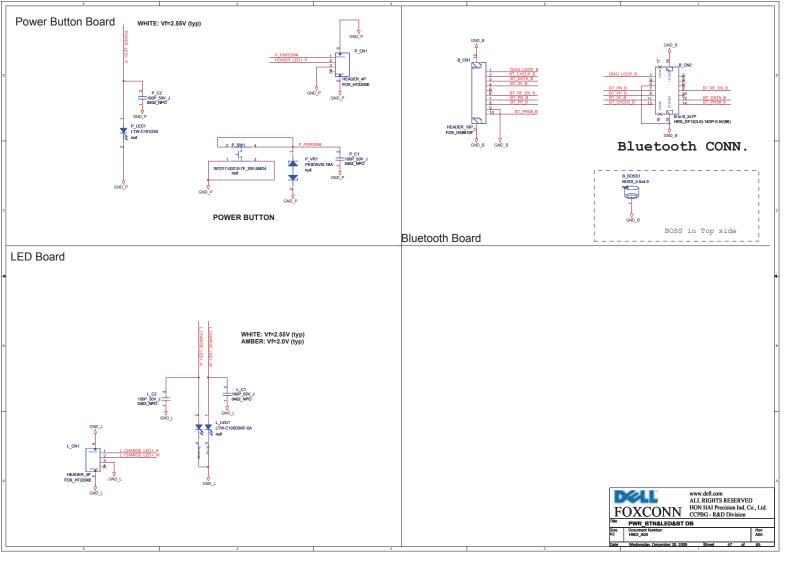


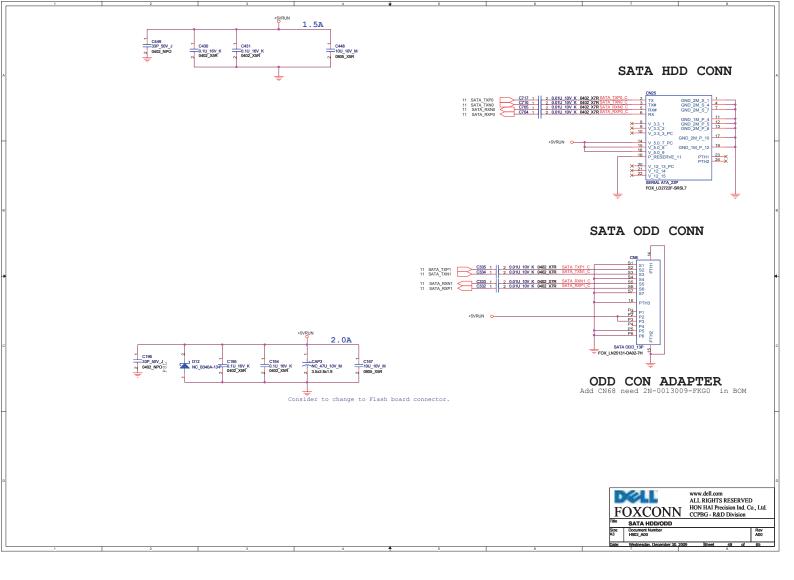


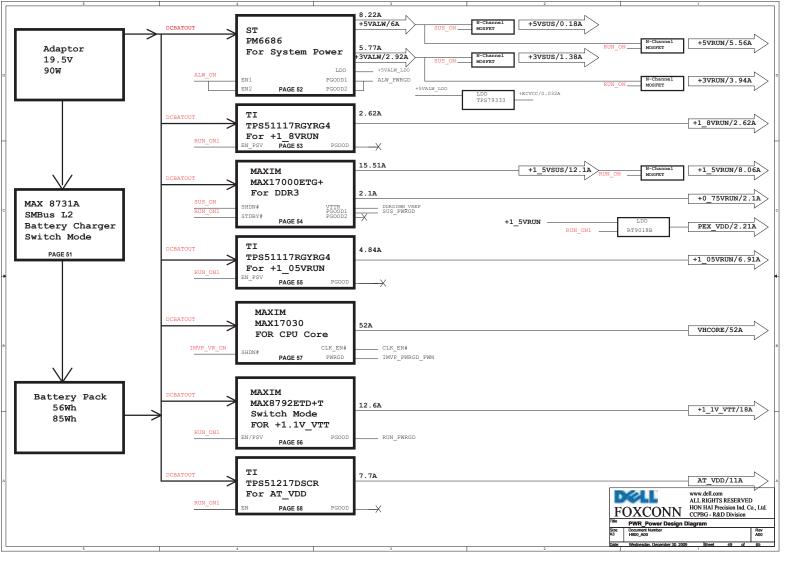


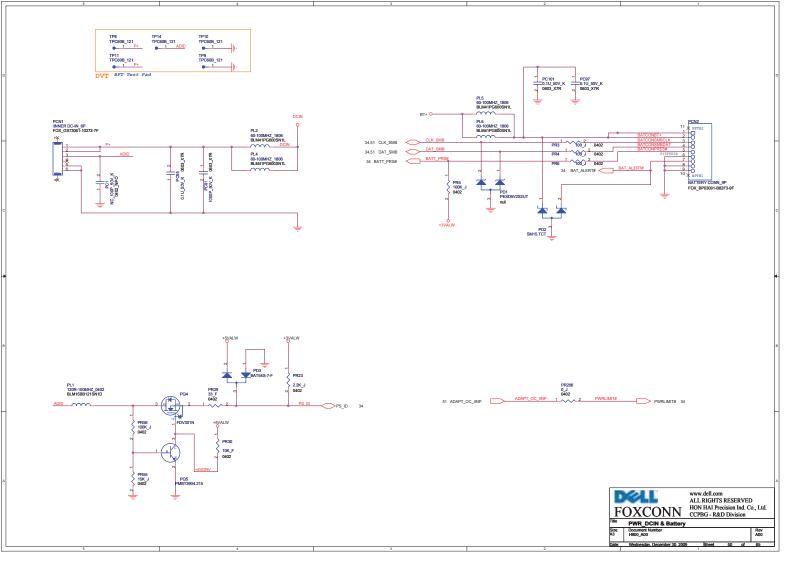


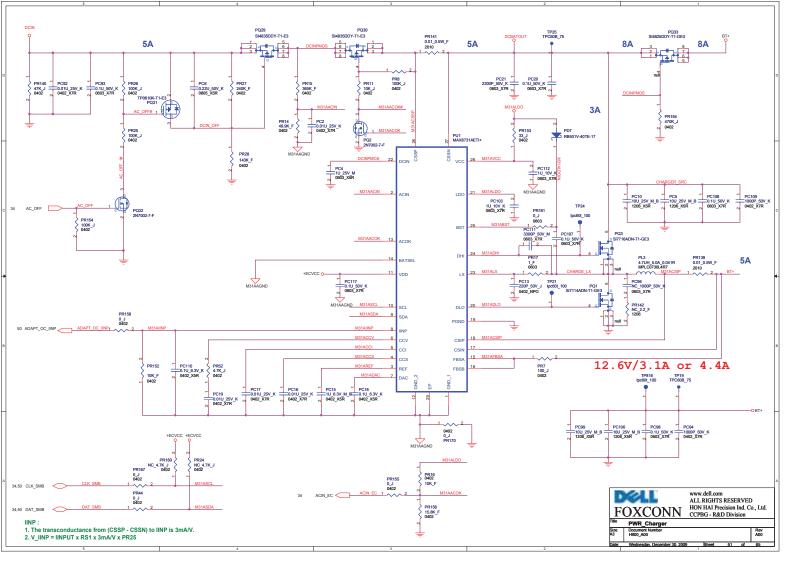


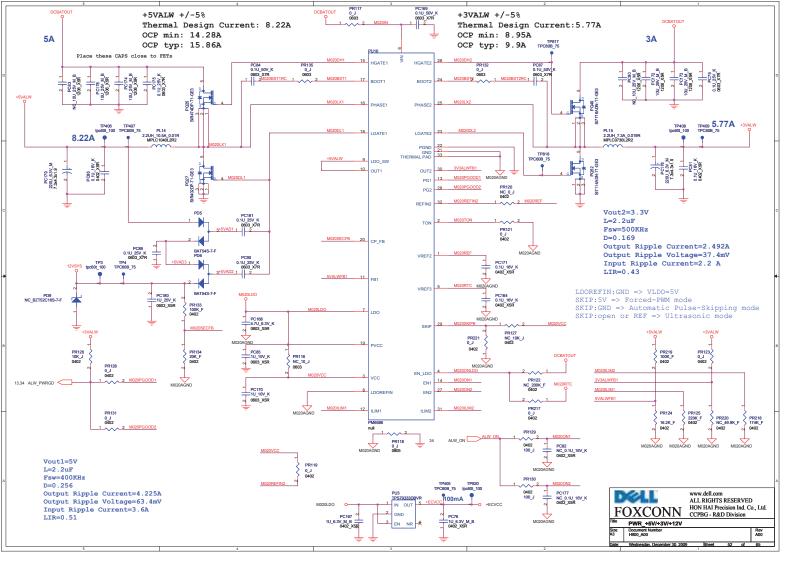


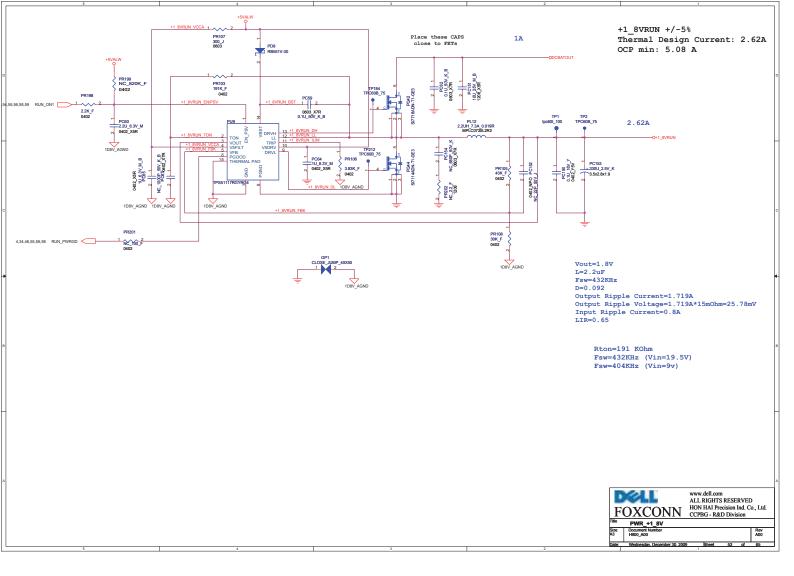


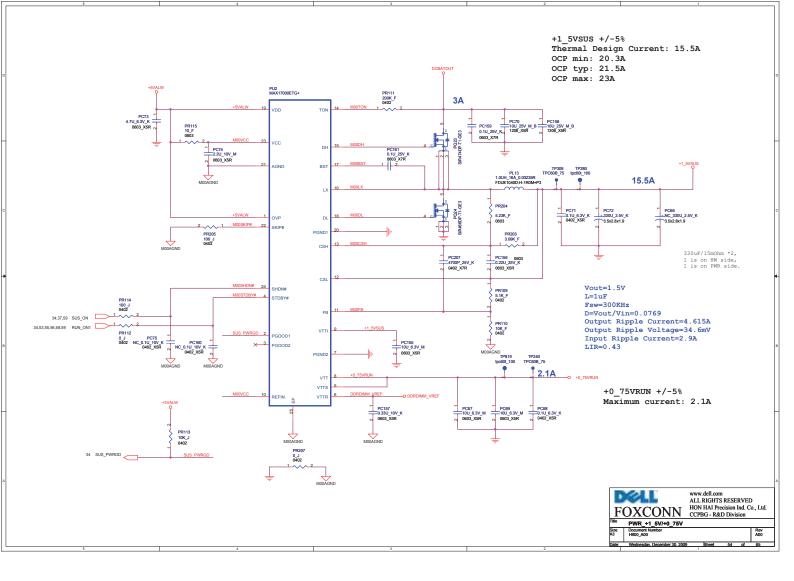


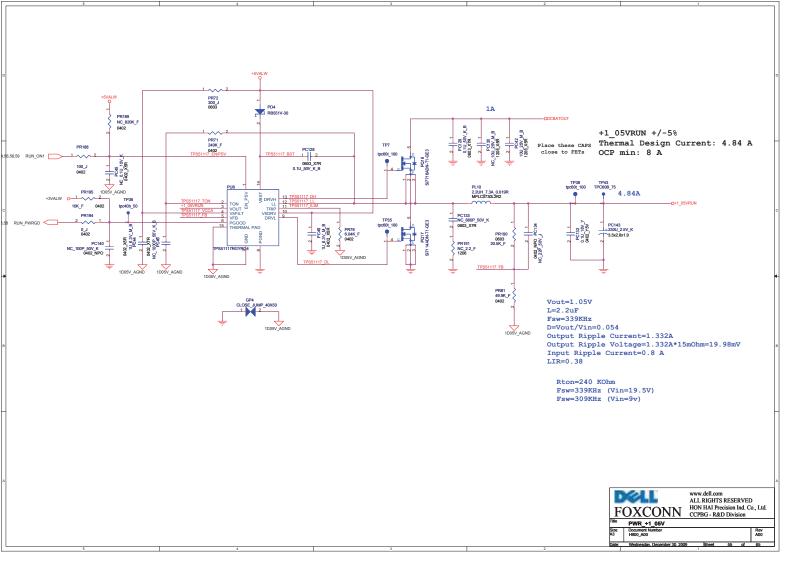


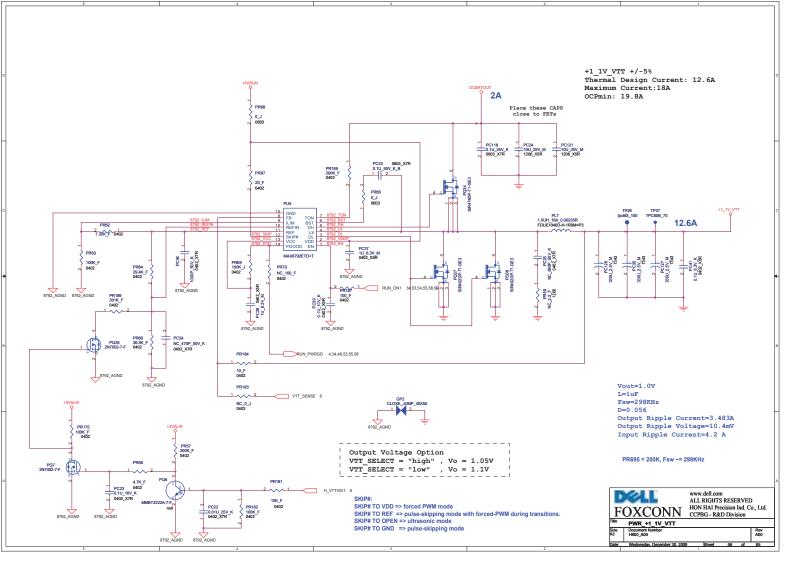


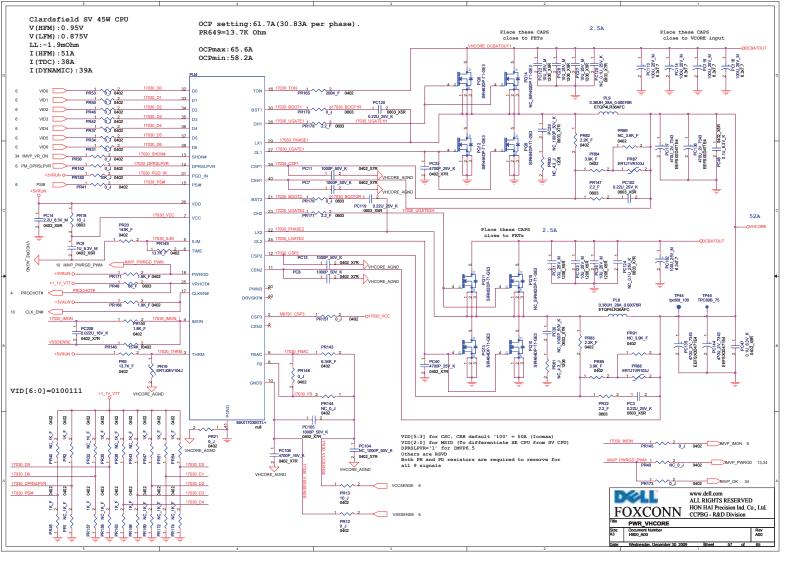


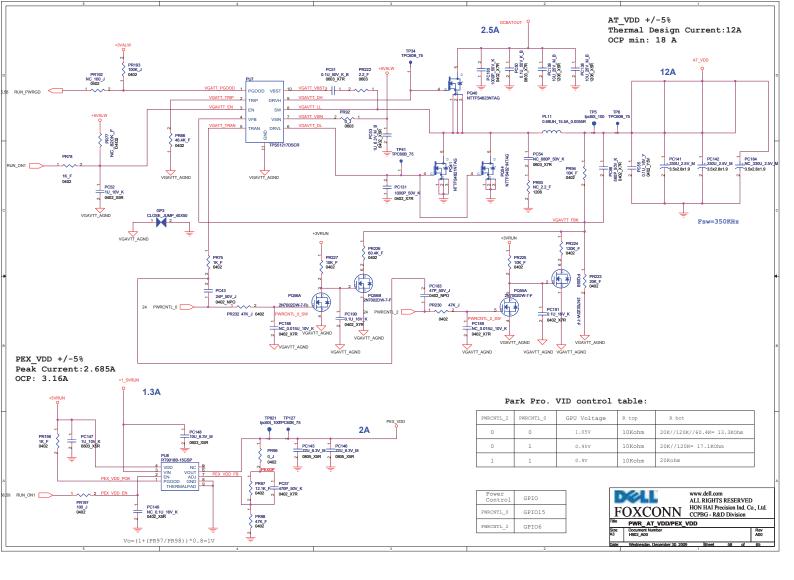


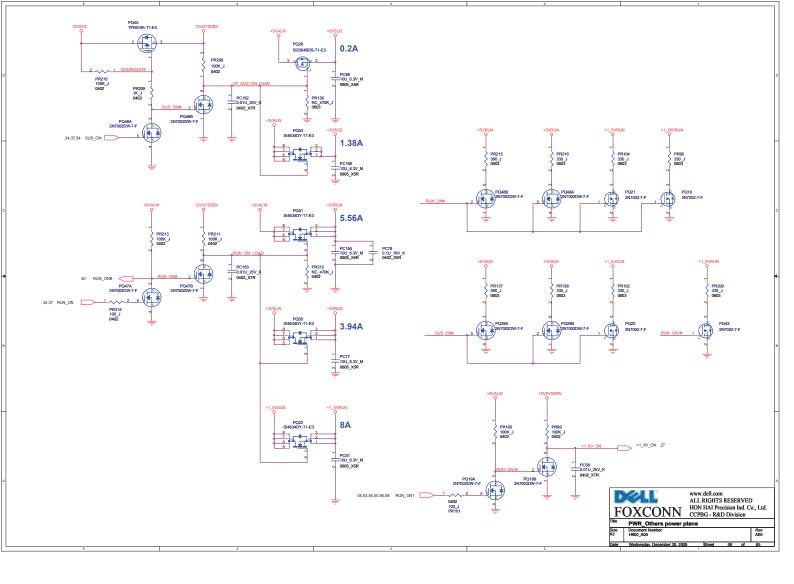


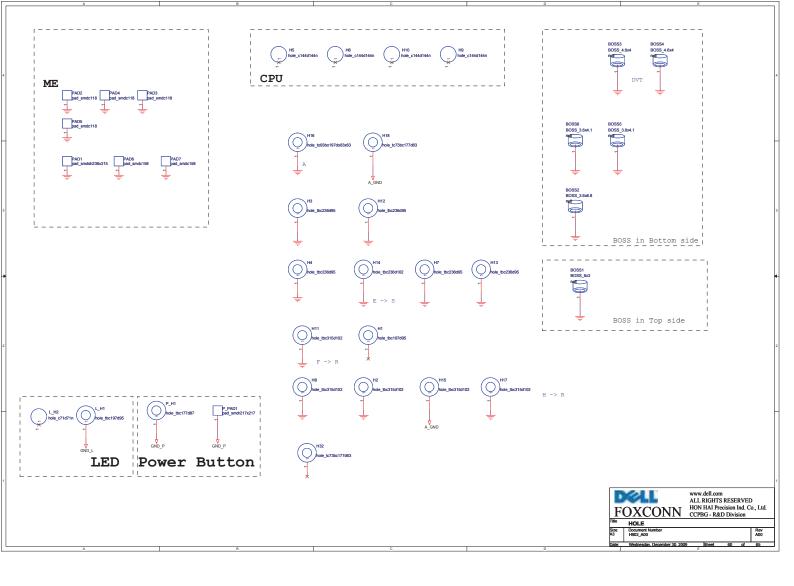












(2009/19/25) P.35 Charge 8139 & R143 from 131 ohm to 40.2 ohm for AMD recommend. P.34 Charge 817 MM2 10-3 connect to DYNAR2 0-3. P.38 Resource 817 S.NOS 2 or rectume DDEF 917 COMBO, C789, CRE1 for AMD recommend. P.31 C. C737, CRE1 for AMD recommend. P.32 N. C737, CRE1 for AMD recommend. P.32 N. C737, CRE1 for AMD recommend. P.33 N. C737, 146, 147 to 11-242201-2200 for PUR recommend. P.31 Charge 253, 137, 146, 147 to 11-242201-2200 for PUR recommend. P.31 Charge 264 to 12-222014-X311 for PUR recommend. P.32 Charge 264 to 12-222014-X311 for PUR recommend. P.33 Charge 264 to 12-22013 to 12-22014-X311 for PUR recommend. P.33 Charge 264 to 12-22013 to 12-22014-X311 for PUR recommend. P.33 Charge 264 to 12-22013 to 12-22014-X311 for PUR recommend. P.34 Charge 164 to 12-22013 to 12-22014-X311 for PUR recommend. P.35 Charge 264 to 12-22013 to 12-22014-X311 for PUR recommend. P.36 Charge 164 to 12-22013 to 12-22014-X311 for PUR recommend. P.36 Charge 164 to 12-22013 to 12-22014-X311 for PUR recommend. P.37 Charge 264 to 12-22014-X311 for PUR recommend. P.38 Charge 264 to 12-22014-X311 for PUR recommend. P.39 Charge 274 to 12-22014-X311 for PUR recommend. P.30 Charge 274 to 12-22014-X311 for PUR recommend. P.31 Charge 274 to 12-22014-X311 for PUR recommend. P.32 Charge 275 to 12-22014-X311 for PUR recommend. P.33 Charge 274 to 12-22014-X311 for PUR recommend. P.33 Charge 274 to 12-22014-X311 for PUR recommend. P.33 Charge 274 to 12-22014-X311 for PUR recommend. P.33 Charge 275 to 12-22014-X311 for PUR recommend. P.33 Charge 275 to 12-22014-X311 for PUR recommend. P.33 Charge 275 to 12-22014-X311 for PUR recommend. P.44 Charge 175 to 12-22014-X311 for PUR recommend. P.45 Charge 175 to 12-22014-X311 for PUR recommend. PUR DURANT PU

H902 DVT

H900 EVT -> DVT (2009/04/27) (2009/03/26) P.4 Change R184 to 1.1K ohm R182 to 3.01K ohm for Intel recommand. Add BT2(CSR) BC_BOSS1 NC for reserve. P.32 Change LVDS connector pin define switch Pin4 $\,$ and Pin10. (Pin4 NC, Pin10 +3VRUN) P.36 Add R27 0 ohm for DVT P.47 Add BT2(CSR) BC BOSS1 NC for reserve. P.41 Change R602, R611, R608, R610 to 1k ohm for Audio headphone noise. (2009/03/27) P.46 Modify WWAN CN5 pin define. P.45 Add F1 and F5 for protection and del PGP7 and PGP8. (2009/04/30) P.32 LVDS CN, change +3VRUN to pin 4, pin3 to NC prevent DCBATOUT short to +3VRUN. P.6 Del R401, R115 for Vcore power plane. P.38 Change TP29, TP46, TP42, TP40, TP39, TP428, TP430 to TPC40B_121. P.50 Change TP8, TP11, TP14, TP10, TP9 to TPC60B_121. (2009/03/31) P.42 Change R588,R589 to 8.2K ohm for 1.5W speaker. L.U. Change IFO, 1F11, TF14, TF1U, TP9 to TPC60B_121. P.44 Change TF412, TP411, TP413 to TFC40T_121. P.39 Change TP12, TP15, TP16, TP17, TP18, TP20, TP22, TP23 to TPC40B_121. P.42 Change TP186, TP185, TP183, TP187 to TPC40B_121. P.34 Change TP480, TP485, TP329, TP479, TP483, TP182, TP333, TP128 to TPC40T_121. P.40 Change R332 to 13.3K for Realtek recommend. P.24 Reserve R382, R383, R617 and R293 0 ohm for Park. P.24 Reserve L71, C785 luF, C786 l0uF, C787 0.luF, L70, C782 luF, C783 l0uF, C784 0.luF for Park. P.46 Change TP414, TP410 to TPC40T_121 and TP13 to TPC40B_121. P.24 Reserve R619, R620 0 ohm for Park. P.38 Change TP47, TP422, TP417, TP37, TP30, TP33, TP32, TP31, TP28 to TPC40B_121. P.27 Add R622 0 ohm for saperate Park schematics P.27 Reserve R618 and R621 Oohm, C512 luF, C515 10uF, and L72 for Park. P.11 Change C736 to 15pF for cystal vendor recommand. P.39 Change C35 and C38 to 18pF for cystal vendor recommand. (2009/04/02)P.26 Reserve L73, C788 1uf, C789 10uf, C790 0.1uf and R623 0ohm for Park. P.34 Del Q28 and R318 2.2k ohm for CPU PC Beep solution (2009/05/5) P.32 Change C65 to 6800pF for LVDS sequence. P.39 Reserve R318 and R384 0 ohm for leakage solution. (2009/04/03) P.27 Reserve R624 150 ohm, R627 0 ohm for Park. P.27 Add R625,R626 0 ohm for Park. P.45 Change F1 and F5 to 1M-F08V05A-0000. (2009/04/06) 11 Stuff R495 for Flash SPI. P.16 Reserve R391 1K ohm for following the CRB. (2009/04/10) P.11 Change PCH SPI_CS# to SPI_ROM_CS#. P.7 Del R55 0 ohm for leakage. P.35 Change U13 to W25X80A. P.34 Change H_PWRGD to H_CPUPWRGD. P.31 Change L61, L62, L63 to 33R100MHz for CRT SI issue. (2009/04/13) P.40 Reserve R628 0 ohm for PC beep. (2009/05/11) P.42 Change R45, R47, R49, R50 to bead L76, L77, L78, L79 for EMI request. P.17 Change C479 to 1uF for Intel recommend. P.24 Reserve R410 and R629 0 ohm for Park. P.32 Change I19 to BLM18BB121SNID to solve AT_DPLL_PVDD Vpp over spec issue. P.32 Change F8 to 467002 (32V-2A_0603) for LVDS VCC protection. P.47 Del BC_CN4,BC_CN3,BC_BOSS1,BC_TP1,BC_TP2 for BT2 board is not necessary. P.24 Reserve R634, R631, R632, and R633 0 ohm for Park. P.24 Del R619 and R620 0 ohm for Park NC. P.42 Change C767, C763, C762, C749 to 0.01uF; C507 to 0.1uF for speaker pop noise. P.25 Change C781 to 1nF for AMD recommend. P.25 Reserve R630 680 ohm and R115 10K PD for Park. P.32 Del R29 Oohm for no necessary. P.36 Del R27 Oohm for no necessary. P.45 Change R384, R34, R52 to close gap PGP4,PGP5,PGP6. P.27 Reserve R635 0 ohm for Park. P.25 Add TP172, TP173, TP174, TP175, TP176 and TP177 for Layout request. P.45 Change F5,F1 to close gap PGP7,PGP8 for un-necessary. P.22 Change R410 Oohm to close gap PGP12. P.60 Change BOSS3 and BOSS4 for ME request. P.17 Del C445 and C463 33pF for unused. P.26 Change R92, R93 Oohm to close gap PGP13, PGP14. hom for unused. P.36 Change R391 Oohm to close gap PGP17. P.45 Del F1, F5, and R31 0 ohm for unused. P.46 Del F2 for unused. (2009/04/15) P.39 Add D15, D16 for solving leakage issue. www.dell.com ALL RIGHTS RESERVED P.46 Reserve R637 and R638 0 ohm for WWAN change (2009/04/23) P.4 Del R196 Oohm for no necessary. **FOXCONN** CCPBG - R&D Division History (2) Document Number H902 A00 (2009/04/24) for Intel recommend. P.4 Add CPU_DET# for Dell PC Beep. Wednesday, December 30, 2009 Sheet 62

H900 EVT -> DVT

P.25 Add R196 0 ohm and change R630 68 ohm to DRAM RST pin for AMD recommend.

(2009/05/14)

P.12 Add R620 0 ohm to GND in Xtal_in for Intel recommend. P.7 Del R407, R399, and R405 0 ohm for 1.1VTT power plane.

(2009/05/20)

P.4 Change R173 to NC for un-used.

P.27 Change C208 from 0.22u 10V to 0.22u 16V for derating issue. P.17 Stuff R268 0 ohm to GND for disable Intel internal LAN.

P.17 Change R237 and R265 from 0603 to 0805 for derating. P.27 Change R146 from 0805 to 1206 for derating.

P.17 Change CAP5 and CAP6 from 35m ohm ESR to 45m ohm ESR.

(2009/06/06)

P.39 Add Q58, Q59, R619, and R639 10K ohm and del D15 & D16 for leakage issue. P.6 Add R401 0 ohm and Add R399, R405, R407, R640 1K ohm NC for C-state debugging.

P.6 Add R641 & R642 0 ohm for controling LAN_CLK_REQ# turn on voltage.

P.34 Add R643 & R644 0 ohm for debugging white screen issue

P.11 Change RTC battery P/N from 1M-BCR2032-LB00 to 1M-BCR2032-LB01.

(2009/07/01)

P.60 Add H32 for ME request.

(2009/07/14)

P.12 Add R645 & R646 2.2K ohm for SMBUS PH.

(2009/07/20)

P.38 Change C33 and C44 from NPO 10% to 5% for PUR recommend.

P.47 Change P_C1, P_C2, L_C1, L_C2 from 10pF NPO 10% to 5% for PUR recommend. P.40 Change C499 and C505 from 12pF NPO 10% to 5% for PUR recommend.

P.11 Change C735 from 12pF NPO 10% to 5% for PUR recommend. P.38 Change C78 and C79 from 15pF NPO 10% to 5% for PUR recommend.

P.11 Change C736 from 15pF NPO 10% to 5% for PUR recommend. P.46 Change C244 and C245 from 47pF NPO 10% to 5% for PUR recommend.

P.39 Add C445 0.1uF for Hipot test.

P.39 Add C445 0.141 lol P.27 Delete R146 Oohm for derating. P.18 Delete R257 Oohm for derating.

P.17 Delete R237 Oohm for derating.

(2009/07/22)

P.17 Change C208 0.22uF from 16V to 25V for derating. P.39 Add C791, C794 1000pF and C795, C796 0.047uF for EMI request.

P.12 Change R303 & R331 from 4.7K to 2.2K ohm NC.

H900 DVT -> PVT

P.34 Add Q28 and NC C478 0.1uF for Sys_shdn#. P.44 Change R467 from 33K to 10K ohm & R472 from 15K to 6.8Kohm for thermal setting.

P.39 NC C26 0.1uF, R14 1K ohm and U2 24C08. Add R612 1K ohm for disable external EEPROM.

P.44 Add C463 100p NC for Thermal sensor vendor recommend.

P.9 Change R51 & R53 from NC to introduce. P.33 Change HDMI connector from $2N\!-\!0019003\!-\!FKG0$ to $2N\!-\!0019002\!-\!MKG0$

H900 PVT -> X-Build

P.31 Change L61, L62, and L63 from 33R to 47R for CRT debug. P.33 Change D5 location to D9 for Safety recommend.

P.11 Change D9 location to D5 for Safety recommend.
P.11 Change R340 & R341 location to R427 & R426 for Safety recommend.

P.24 Change R426 location to R341 for Safety recommend.

P.45 Change R427 location to R340 for Safety recommend.

P.32 Change U5 location to U4 for Safety recommend. P.10 Change U37 location to U40 for Safety recommend.

P.45 Change U4 & U40 location to U5 & U37 for Safety recommend. P. 4 Change U17 from 14-MC74VHC-1G04 to 14-74AHC1G-1400 for L6 recommend.

(2009/08/07)

P.31 Change C646 & C640 from 47p to 22p.

(2009/08/20)

P.30 Change L1 to LanKom 1T-1LG2425-P100.

P.20 Change R61 to NC for DDR Intel recommend. P.21 Change R66 to NC for DDR Intel recommend.

(2009/08/22)

P.20 & 21 Del R146 & R237 for customer recommend. P.20 Reserve R23 & R27 1K ohm for intel DDR3 M1 solution.

P.21 Reserve R29 & R31 1K ohm for intel DDR3 M1 solution.

P.24 Add R636 0 ohm for EMI recommend. P.24 Add Cap7 330 uF for debugging WLAN issue.

(2009/08/25)

P.44 Add R637, R638, R645 & R646 0 ohm for Intel recommend.



н900	Power (Change	Histor	cy					
Number	Date	Page	Title	Issue	Description	Version			
1	2009/04/10	P.55	+1_05VRUN	1.05V Vripple over spec.	Change PC143 from 220uF 2.5v 35m Ohm(1C-31R0227-MX00) to 330uF 2.5v 15m Ohm(1C-33U0337-KX00).	X01			
2	2009/04/13	P.51	Charger	Change PR152 for ADAPT OC function.	Change PR152 from 8.45K 0402 1%(1R-0008451-F200) to 10K 0402 1% (1R-0000103-F200)	X01			
3	2009/05/06	P.57	VCORE	 	Add PC7 :470pF 50V X7R 0402(1C-2B20471-K000) Add PC106 :4700pF 16V X7R 0402(1C-2B20472-K002) Add PC209 and PC30 :1000pF 50V X7R (1C-2B3012-MX00) Add PC29 and PC30 :1000pF 50V X7R (1C-2B3012-MX00) Add PR60 and PR61 :4.3 0hm 1206 5%(1R-000043X-J600) Del PQ14 and PQ15 SiR462DP-T1-GE3 (17-S1R462D-PT00) Change PR12 from 10 0hm 0402 5%(1R-0000100-J200) to 0 0hm 0402 5%(1R-0000000-J200) Change PR143 from 7.15K 0hm 0402 1%(1R-0007151-F200) to 6.34K 0hm 0402 1% (1R-0003431-F200) Change PR82 and PR83 from 2.7K 0hm 0402 1%(1R-0000272-F200) to 2.2K 0hm 0402 1% (1R-0000222-F200) Change PR84 and PR85 from 4.02K 0hm 0402 1%(1R-0004021-F200) to 1.69K 0hm 0402 1% (1R-0001691-F200)	x01			
4	2009/05/06	P.58	AT_VDD	Changing H-S,L-S Mosfets and boost resistor for solving ring issue.	Change PQ40 from Si7716ADN(17-S17716A-DN00) to AON7402L(17-AON7402-L000) Change PQ41 from Si7114ADN(17-S17114A-DN00) to AON7700(17-AON7700-0000) Change PR222 from 0 Ohm 0603 1%(1R-0000000-J300) to 1 Ohm 0603 1%(1R-000010X-F300)	X01			
5	2009/05/07	P.54	+1_5VSUS	Modifying OCP setting for +1_5VSUS.	Change PR204 from 4.87K 0603 1%(1R-0004871-F300) to 5.23K 0603 1%(1R-0005231-F300) Change PR203 from 3.24K 0603 1%(1R-0003241-F300) to 3.09K 0603 1%(1R-0003091-F300)	X01			
6	2009/05/11	P.56	+1_1V_VTT	Change remote sense detection from CPU to output Cap.	Add PR184 10 Ohm 0402 1%(1R-0000100-F200) Delete PR183 0 Ohm 0402 5%(1R-0000000-J200)	X01			
7	2009/05/12	P.50	PSID	Change PQ4 to high ESD protection (6000KV).	Change PQ4 from 2N7002K(17-2N7002K-0001) to FDV301N(17-FDV301N-0000).	X01			
8	2009/05/12	P.55 P.56	+1_05VRUN +1_1V_VTT		Delete PR70 100 Ohm 0402 1%(1R-0000101-F200) Add PR195 10 KOhm 0402 1%(1R-0000103-F200) Add PR194 0 Ohm 0402 5%(1R-000000-J200)	X01			
9	2009/05/13	P.57	VCORE	PROCHOT# signal pull-up resistor is 56 ohm in IMVP side.	Change PR48 from 56 Ohm 0603 1%(1R-0000560-J300) to 68 Ohm 0603 1%(1R-0000680-F300)	X01			
10	2009/05/20	P.58	PEX_VDD	Modify feedback capacitor for improving loop response.	Change PC57 from 0.01uF 0402 25V X7R(1C-2B20103-M000) to 470pF 0402 50V X7R (1C-2B20471-K000)	X01			
11	2009/05/20	+	DC_IN		Change PR28 from 47KOhm 0402 5%(IR-0000473-J200)to 100KOhm 0402 5%(IR-0000104-J200) Change PC6 from 0.1uF 0603 50V(IC-2B30104-K000) to 0.22uF 0603 25V X5R (IC-2B30224-K400)	X01			
12	2009/05/26	P.54	+1_5VSUS	Add a capacitor between CSH and FB for improving jitter issue.	Add PC207 4700pF 25V 0402 X7R 10%(1C-2B20472-K001)	X01			
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н900	Power C	hang	e Histo	ry					
Number	Date	Page	Title	Issue	Description	Version			
13 I	2009/06/18	P.57	V_CORE	Change GND design for C-state issue	Change PR21.1 to PGND. Change PR21.2 to AGND. Change PC14.2 to PGND.	1 1 1 X02 4			
14	2009/07/02	P.57	v_core	Change boost resistor to reduce ring of Mosfet. Add feedback capacitor to ruduce groun noise.	Change FR178 from 0 Ohm 0603 5%(1R-0000000-J300) to 2.2 Ohm 0603 1%(1R-000022X-F300) Change FR177 from 0 Ohm 0603 5%(1R-0000000-J300) to 2.2 Ohm 0603 1%(1R-000022X-F300) Add PC7: 1000pF 16V X7R(1C-2B20102-K001). Add PC11: 1000pF 16V X7R(1C-2B20102-K001). Add PC12: 1000pF 16V X7R(1C-2B20102-K001). Add PC12: 1000pF 16V X7R(1C-2B20102-K001).	x02			
15	2009/07/06	P.51	Charger	Change rating voltage from 25V to 50V and size from 0603 to 0805 for Capacitor(PC6).	Change PC6 from 0.22uF 25V X5R 0603 10%(1C-2B30224-K400) to 0.22uF 50V X5R 0805 10%(1C-2B70224-K600)				
16	2009/07/10	+ P.57 	V_CORE	Modify DCR feedback and IMON setting.	Change F84 and FRES-from I. & FK 6467 18[1R-7001 69]-F200) to 3.3% 0402 18[IR-700390]-F200) To Change F8150 from 10X 0402 18[IR-90001032-F200] Change F8150 from 10X 0402 18[IR-90001032-F200] Change FC208 from 0.1uF 6.3% 0402(1C-2B20104-K101) to 0.022uF 16V 0402 X7R(IC-2B20223-K000) Change FR146 from 12K 0402 18(IR-0000123-F200) to 15.4K 0402 18(IR-0001542-F200)	X02			
17	2009/07/20	P.59	Other power	Add dicharge path for 1_5VRUN and 1_05VRUN	Add PR104:330 Ohm 0603 5%(IR-0000331-J300) Add PR95:330 Ohm 0603 5%(IR-0000331-J300) Add PQ21:Z070027-F SOT-23(17-Z070027-F000) Add PQ18:ZN7002-7-F SOT-23 (17-ZN70027-F000)	X02			
18	2009/07/24	P.57	V_CORE	Add AL capacitor to reduce acustic noise.	Add PC18:EEEFK1E101XP,100uF,25V,20%, § 6.3*7.7,0.34ohm(1C-1XX0107-M400) Add PC182:EEEFK1E101XP,100uF,25V,20%, § 6.3*7.7,0.34ohm(1C-1XX0107-M400)	x02			
19	2009/09/25	P.58	VGA_CORE	Add more GPIO pin for VAG 4 level controller	Add NC_PC187,NC_PC188,NC_PC189 PR230,PR231,PR232, © 00hm Remove PR79, PR80	x02			
20 1	2009/09/25	P.58	 	Change AOS MOS to ON MOS for reducing risk of induce voltage	Change PQ40 PQ41 and PQ54 to ON MOS 4823 and 4821.	 			
21	2009/11/19	P.58	VGA_CORE	 EMI request add one cap	Add PC185 1000pF	 			
22	2009/11/19	P.58	USA_CORE	 Reduce inductor current when VID change	change PR230, PR232, from 0 to 47K. change PC188, PC189, from 0.047wF to 0.015wF. PC56 from 22pF to 560pF NC PC131, PC141, PC142, from 330wF 15mohm to 330wF 9mohm. Add NC_PC190,NC_PC191				
+		! L	! !	 	change PR86, to 46.4K for OCP 15A	 			
23	2009/11/19	P.58	VGA_CORE	 TI suggest reducing short through risk 	change FR222, from 1 ohm to 2.2 ohm	1			
24	2009/11/19	P.58	VGA_CORE	Remove unused GPIO pin	FOXCONN HON HAI Pr	S RESERVED ecision Ind. Co., Ltd.			
24 I	2009/11/27	P.58	VGA_CORE	R C delay as Dell request	NC_PC188, PC_PC189 and add PC190, PC191 0.1uF See December History (2) See December History (2) See December History (3) History (4) History (4) History (4) History (4) History (5) History (6) History (7) History (7) History (8) Histo	Rev A00			
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